

EUSO-BALLON

Un détecteur de rayons cosmiques embarqué dans un ballon stratosphérique

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Les enjeux de la mission EUSO-Ballon, précurseur de JEM-EUSO sur l'ISS

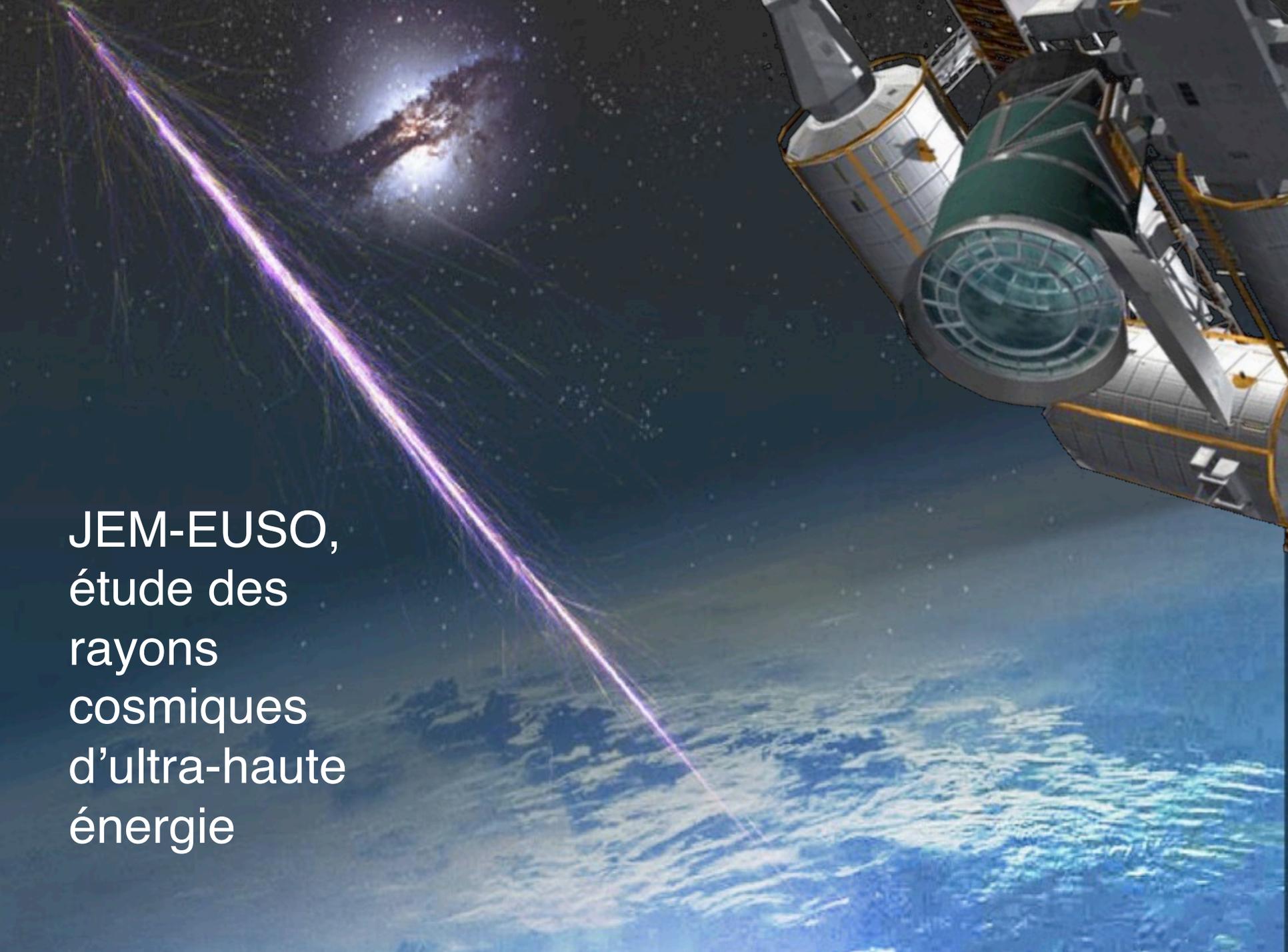
Le projet international EUSO-Ballon 1^{er} vol : l'histoire de trois ans d'aventures

La campagne de vol EUSO-Ballon à Timmins (Ontario, Canada) en août 2014

Résultats et publications

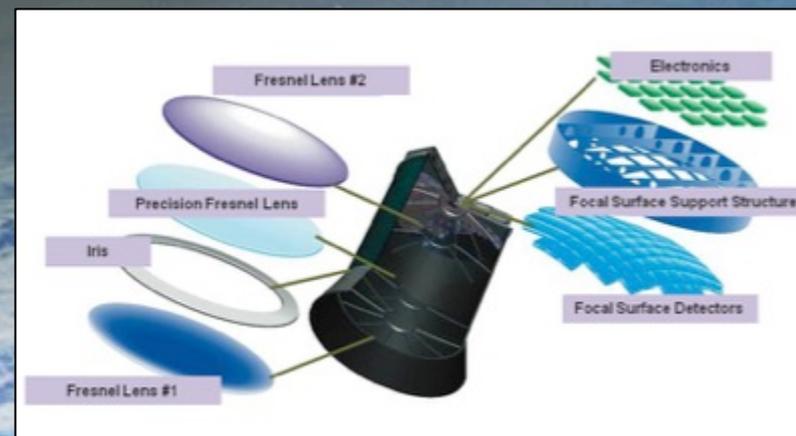
Les perspectives (second vol en Nouvelle-Zélande, Mini-EUSO dans l'ISS)



A detailed illustration of the JEM-EUSO satellite in space. The satellite is a complex structure with various modules, including a large green cylindrical detector and a white cylindrical component. It is positioned in the upper right corner of the frame. The background features a vast expanse of space with a prominent purple and blue cosmic ray shower particle track extending from the top left towards the center. Below the satellite, the Earth's surface is visible, showing a blue ocean and white clouds. In the upper left, a bright, glowing nebula or galaxy core is visible against the dark background of space.

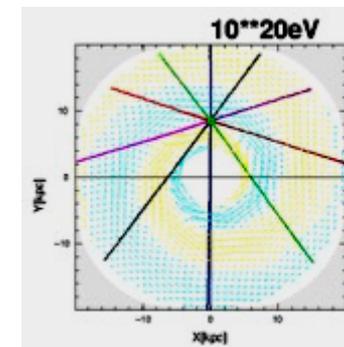
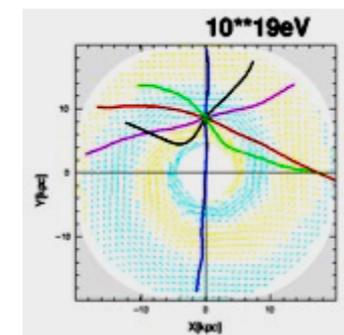
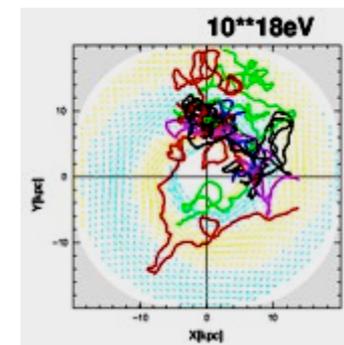
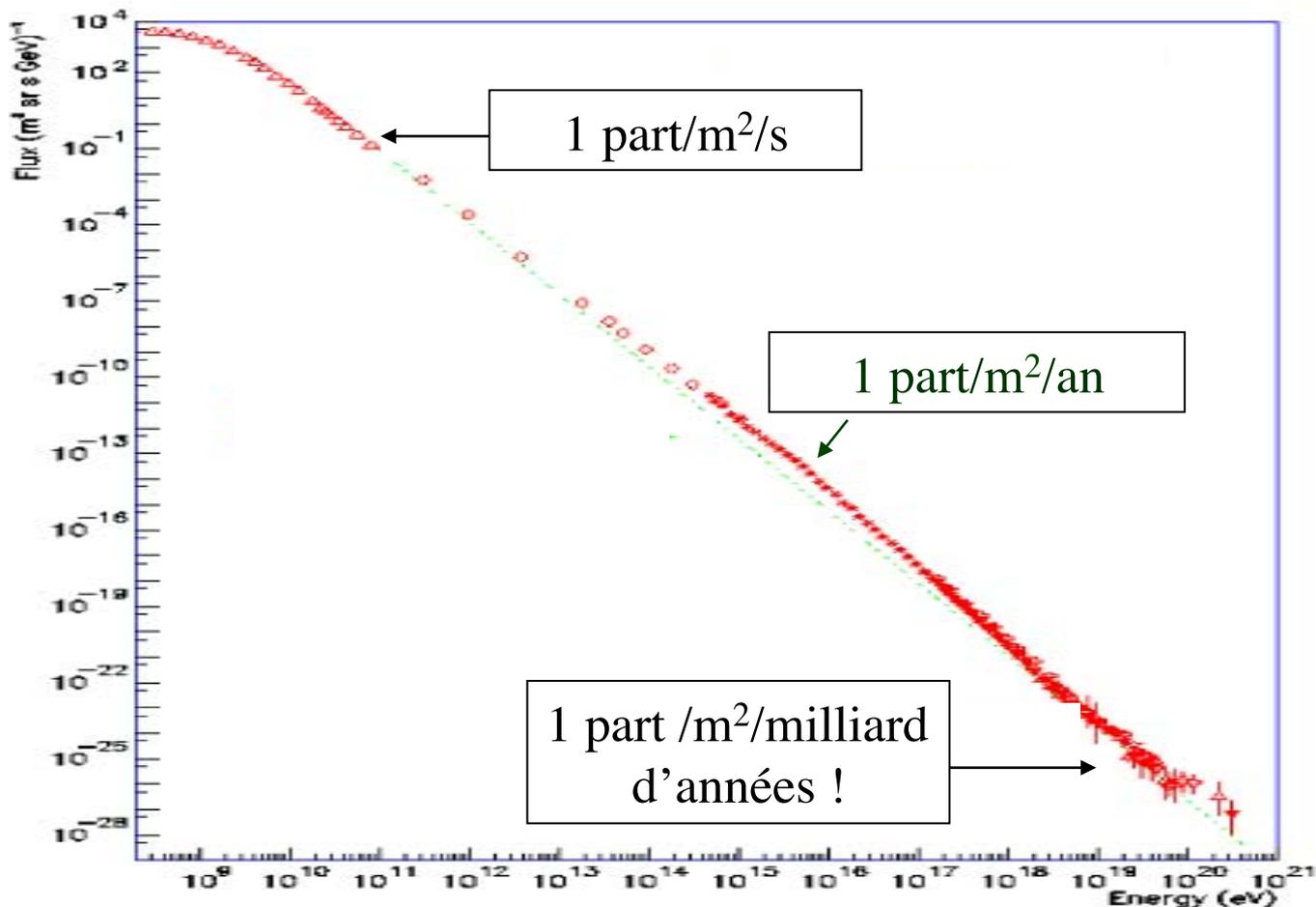
JEM-EUSO,
étude des
rayons
cosmiques
d'ultra-haute
énergie

JEM-EUSO, un télescope à Rayons Cosmiques sur l'ISS





JEM-EUSO: détecter depuis l'espace les rayons cosmiques d'ultra-haute énergie (les moins déviés)

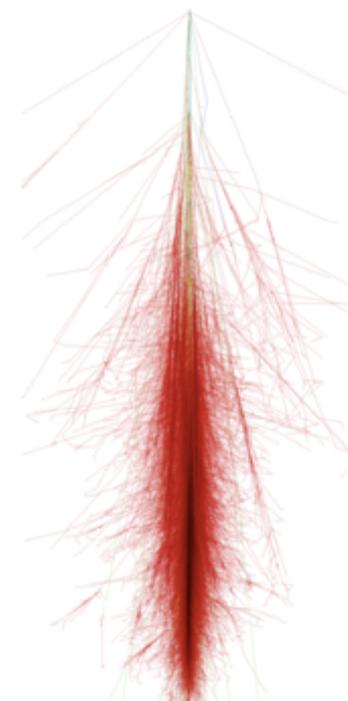
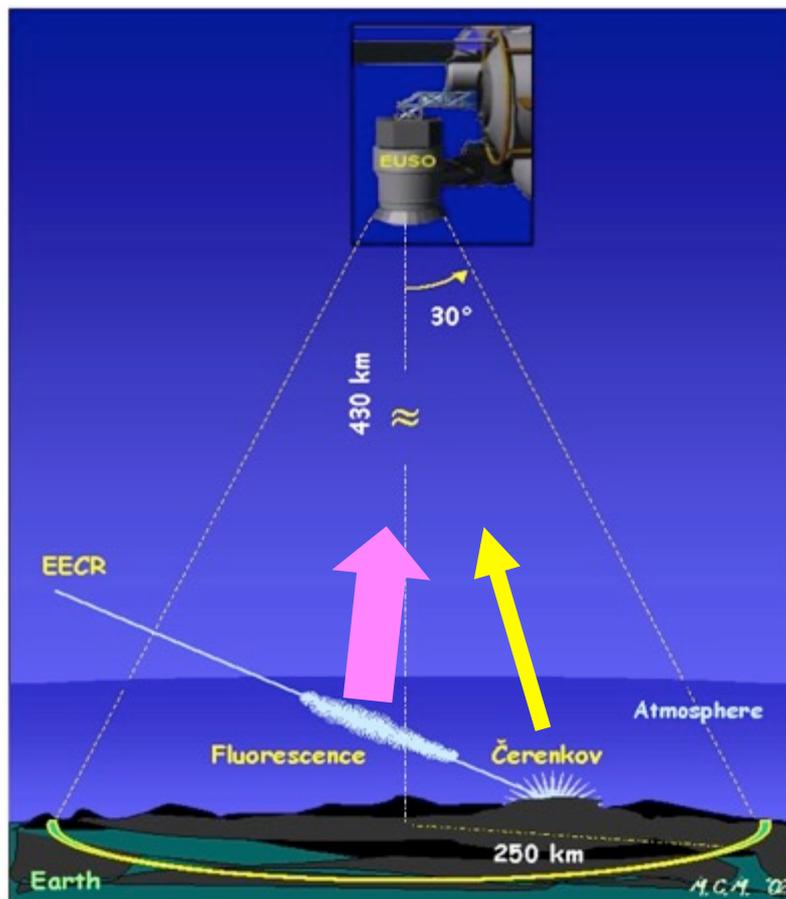
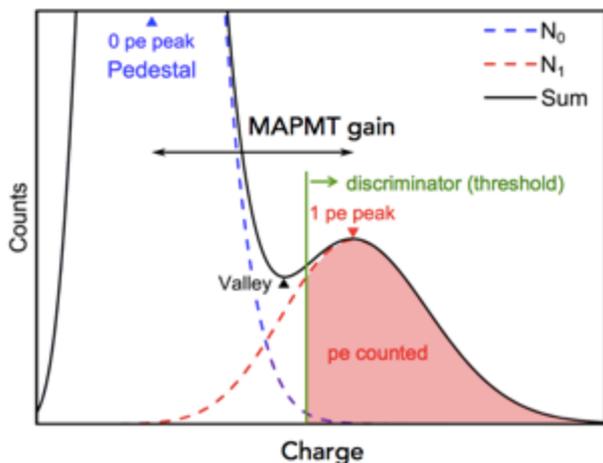




Détecter les rayons cosmiques d'ultra-haute énergie par la lumière de fluorescence émise dans l'UV, suite au développement dans l'atmosphère d'une gerbe de particules secondaires (GTU = 2,5 μ s)

Volume de détection considérable !
Surface au sol : 190 000 km²

Comptage de photon



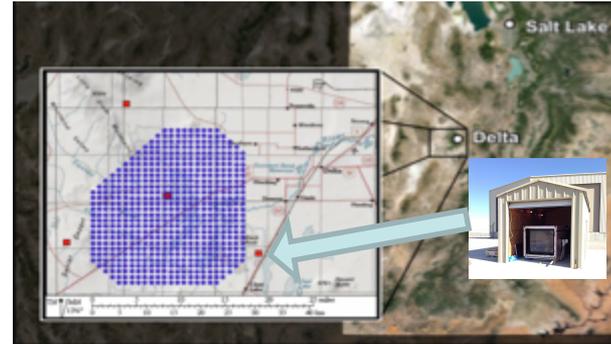
Ne fonctionne que les nuits sans Lune...



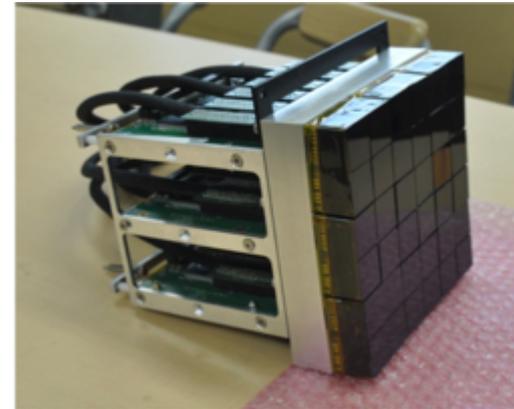
EUSO-Ballon (France) Un pathfinder dans un ballon stratosphérique 2014



EUSO-TA (Japon) Un pathfinder au sol (Utah) 2015

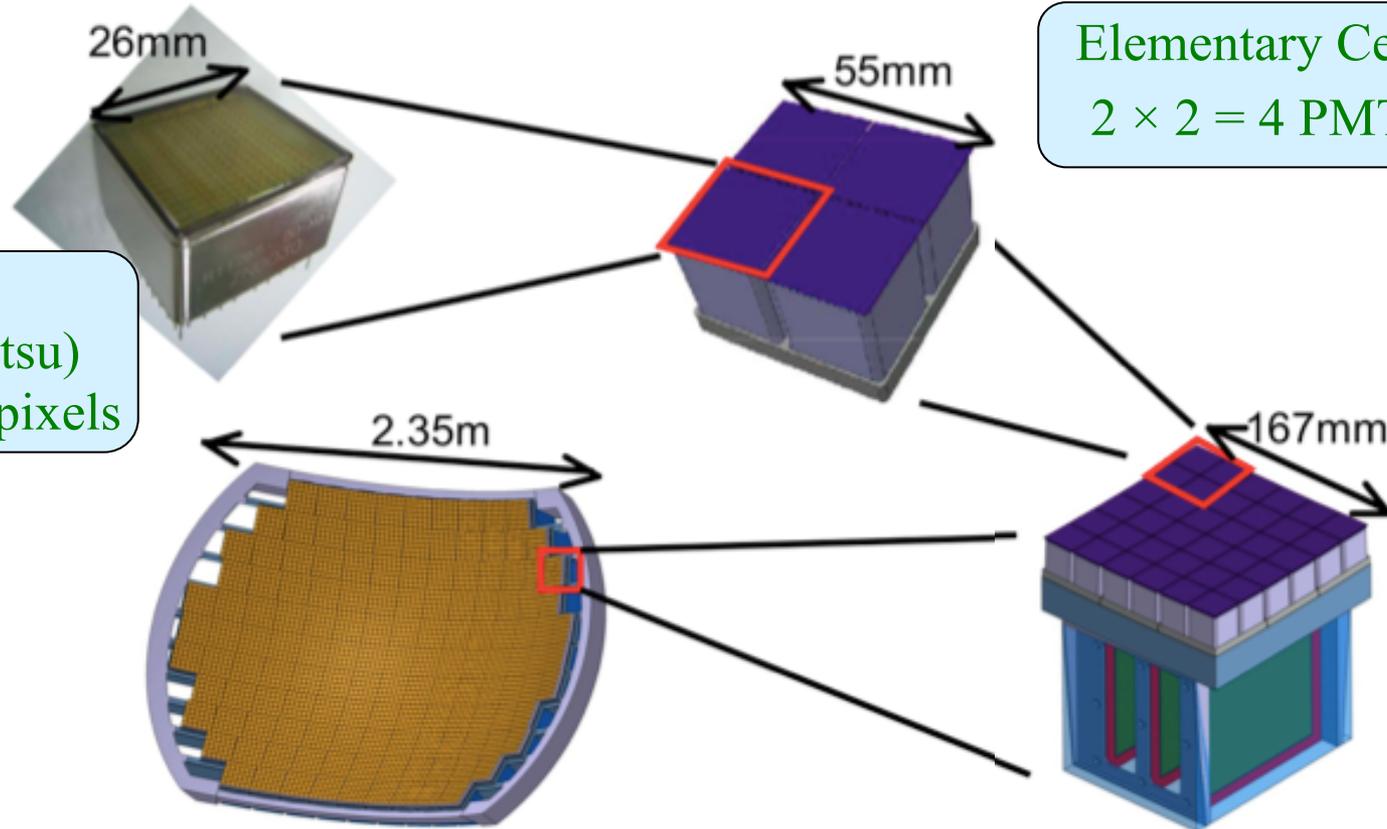


Mini-EUSO (Italie+Russie) Un pathfinder dans l'ISS 2017





Surface de détection: tubes photo-multiplicateurs



MAPMT
(Hamamatsu)
 $8 \times 8 = 64$ pixels

Elementary Cell (EC)
 $2 \times 2 = 4$ PMTs (flat)

Focal surface (FS)
 $137 \text{ PDM} = 4932 \text{ PMT} = 315\,648$ pixels

Photo-Detection Module (PDM)
 $3 \times 3 = 9$ EC (curved)



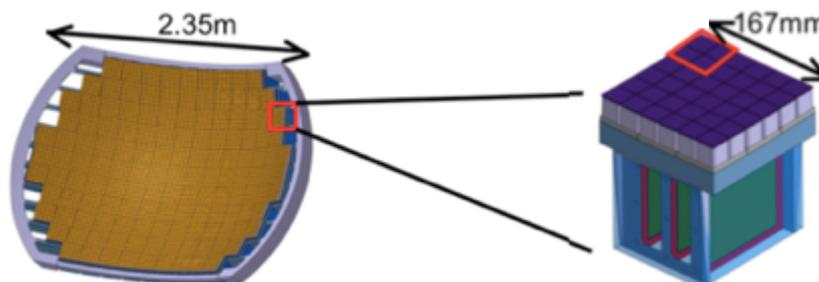
Idée d'un projet éclairreur pour la mission JEM-EUSO en mai 2011



JEM-EUSO

137 PDM

1 PDM



EUSO-Balloon,
a.k.a. α -EUSO

... avec trois objectifs hiérarchisés (pour plusieurs vols)

- Objectif n°1 : prouver la validité du concept, et valider la technologie (en augmentant le degré de maturité TRL des sous-systèmes)
- Objectif n°2 : mesurer le bruit de fond UV (pour différents albédos)
- Objectif n°3 : détecter des événements physiques (réels et/ou simulés)

Les points clés EUSO-Ballon :



14 Sept. 2011 : kick-off meeting pour le démarrage de la Phase A

- Phase A d'octobre 2011 à mars 2012.
- En avril 2012, le CNES accorde le démarrage de la phase B à la condition d'un renforcement de la gestion de projet avec l'arrivée d'un chef de projet global dédié.
- En mai 2012, la gestion de projet est confiée à l'APC (après discussions CNES/APC).
- En septembre 2012, Cellule Suivi de Projet (CSP) EUSO à l'APC.
- **Projet ballon très court (proche R&D) ≠ projet satellite : intention commune de trouver un compromis dans le management par la qualité.**

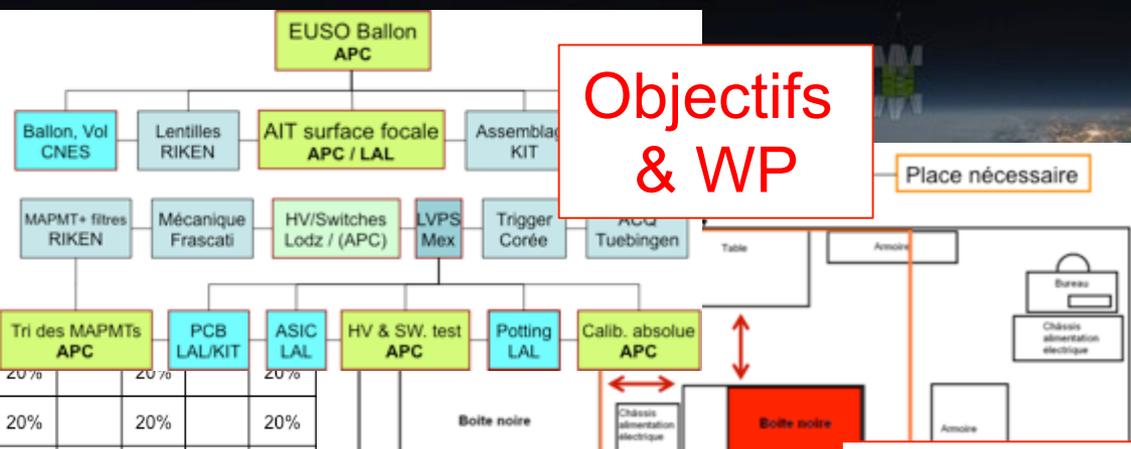
CSP EUSO à l'APC

Tâche	Nom	Corps	Service/ Groupe	2012-S1		2012-S2	
				D	A	D	A
Chef projet Ballon	G. Prévôt	IR	TF	60%		80%	
Syst				20%		70%	
Docu				20%		20%	
Elec				20%		20%	

Cahier des charges

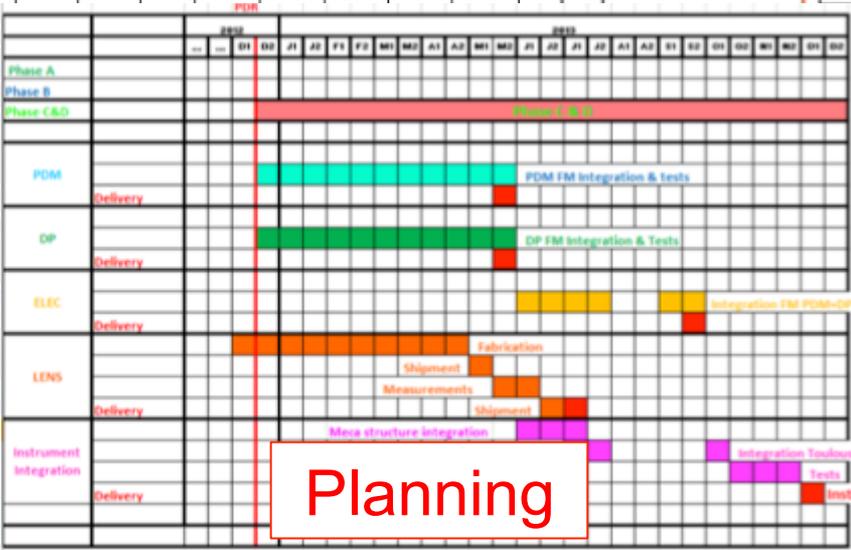
Mesures	C.Blaskley	PhD	AHE	30%			
Gestion	I. Citerne	T	Admin.	5%			
CAO Mécanique	A. Kovacs	IE	Méca	10%			
AIT Mécanique	G.Des que			0%			
Cablage	P. Tardoy		Elec	10%			

Equipe



Objectifs & WP

Place nécessaire

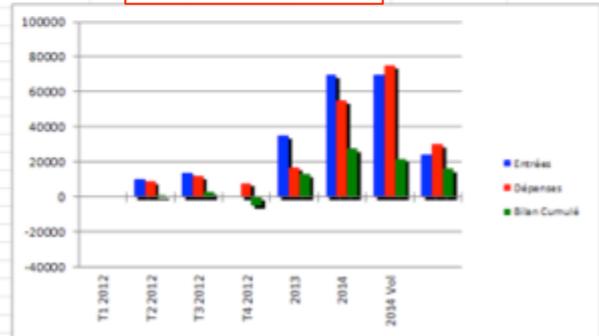


Planning

Espace & Matériel

Suivi Budget Projet et Budget Prévisionnel EUSO Ballon				
Solde Année 2011				
Mois	Entrées	Dépenses	Bilan/mois	Bilan Cumulé
T2 2011	0	0	0	0
T1 2012	10000	9000	1000	1000
T2 2012	14000	12000	2000	3000
T3 2012	0	8000	-8000	-5000
T4 2012	35000	17000	18000	13000
2013	69 500	55000	14500	27500
2014				22000
2014 Vol				16000
Total				

Budget



Capabilité (1 à 5)	Gravité G (1 à 5)	Criticité (P/G)	Solutions + commentaires
3	3	6	Compromis entre techno + simple et retard
3	3	6	
3	3	6	Retard
2	2	4	Retard et cout
3	3	6	Suivi des développements du LAL et APC
6	6	6	Retard, difficultés
6	6	6	Retard
2	3	6	Réséne ou retard
2	2	6	Pas de vol au dessus de la

Risques

Faits marquants :

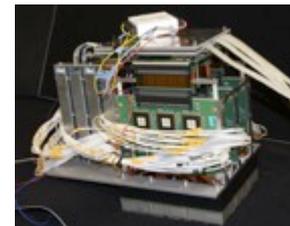
- Projet court
- Premier vol ballon de collaborati
- Technologie principale déjà maît
- Bonnes retombées techniques :
 - Système de HT à très faible consommation
 - Switches ultra-rapides pour adapter le gain des MAPMTs
- Bonnes retombées scientifiques :
 - Mesures de g
 - Mesure précis
- Bonne visibilité
 - Gestion de pro

Conclusions

Modifications



Objectifs des vols (définis durant le kick-Off meeting et accompagnés d'un document de définition instrument et d'un document de spécifications techniques):



Niveau A : Test à l'échelle 1 de l'ensemble de la technologie JEM-EUSO = OBJECTIF PREMIER VOL

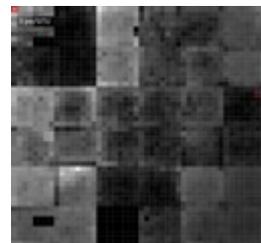
Alimentation haute-tension, commande des switches HT pour la réduction ultra-rapide du gain des PMTs, électronique de front-end (ASICs, FPGA...)

Hardware et software pour les triggers et la reconnaissance des gerbes



Niveau B : Recueil de données et étude du bruit de fond dans des conditions similaires à JEM-EUSO

Avec une résolution suffisante → taille du pixel au sol < celle de JEM-EUSO, acquisition de données type JEM-EUSO depuis une plateforme de type spatial, test et optimisation des algorithmes de trigger en conditions réelles et variables



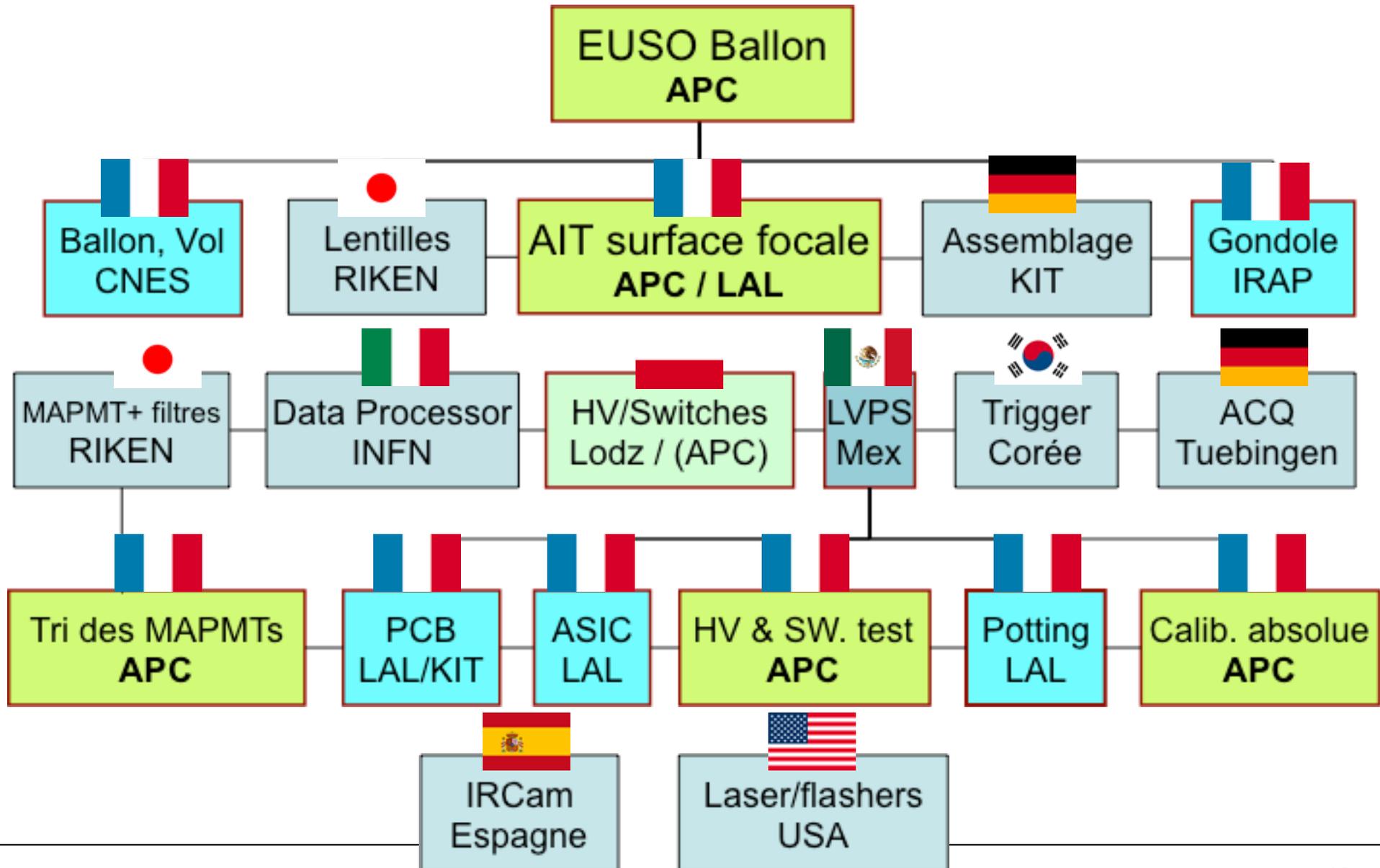
Niveau C : Mission précurseur

Première détection d'une gerbe de rayon cosmique par le dessus ?

Détection d'événements induits par laser ou flashes ?



Organigramme (formalisé dans la note d'organisation) avec WBS



PBS (formalisé dans le plan de développement) -> fiches de tâches

Sub-System	Component	Maturity, Development Status	Direct use for EUSO-B or adaptation required	Need for an Engineering Model (YM)	FM availability and place for production
TLS	Lenses	Industrial production Under control	The produced circular lenses need to be cut in a square	No	To be produced by RIKEN
Photo Detector	UV-Filter	Industrial production Under control	Direct use	No	Under production
	MAPMT	Industrial production Under control	Direct use	No	Already produced
EC Unit	ASIC	Produced for JEM EUSO Project and used on UFFO	Direct use	No	ASIC is produced. Packaging to be done. => LAL
	EC-Dynode board	New design for EUSO. Done.		Mechanical mock up to check holes fitting. Then, flight production	To be produced by LAL
	EC-Anode board	New design for EUSO. Done.			To be produced by LAL
	EC-ASIC board	New design for EUSO. Done.		Mechanical mock up + proto PCB, then flight production	To be produced by LAL
	EC-HV board	New design for EUSO. Done.		Proto model TBC. Depend on the design choice.	To be produced by KIT/Germany
	HV-Cocktail Walton and Switches	Design done for JEM EUSO. Tests done.	Direct use TBC. The size has to match the one available for EUSO	Eng. models developed in Poland laboratory	To be produced by NCBU/Poland
	Assembled and potted EC Unit	New design. Proto EC on going to be potted.		Yes => A mechanical mock up and a proto EC	To be produced under LAL responsibility
PDM Board	Configured FPGA	Version done for UFFO. VHDL to be slightly modified for EUSO	VHDL to be modified. Minor changes.	Will be tested on the PDM board proto model.	To be produced by EWHAKorea
	PDM Board	A design has been done for UFFO. Adaptation to do for EUSO	Minor changes (modification to be done to fit with EUSO connecting)	Proto model and then flight production.	To be produced by EWHAKorea
PDM-LVPS	PSB board	Design done for JEM-EUSO.	Possibly minor adaptation for EUSO: input voltage from 24	Proto model and then FM	To be produced by UNAM/Mexico
CPU	Processor	Off the Shelf	Direct Use	No	To be produced by INF/Naples
OCB	Configured FPGA	Done (Vites-4-FX140)	Direct use	Proto model and then FM prod	To be produced by IATI/Germany
	OCB Board	Design on going	Direct use	Proto model and then FM prod	To be produced by IATI/Germany
	Mass Storage	Off the shelf	Direct use	No	To be produced by UNAM/Mexico
DP-LVPS	PSB board	Design done for JEM-EUSO and for EUSO B	Modifications to be done to adapt to increase power	Proto model and then FM	To be produced by UNAM/Mexico
HK	HK board	Brand new design Done	Direct use	Proto model and then FM	To be produced by UNAM/Mexico
Clocks CPU	CPU	Off the Shelf Done	Direct use	No	To be produced by Naples/INF
	Clock board	Done	Direct use	Proto Model and FM prod	To be produced by Naples/INF
	GPS	Off the shelf	Direct use	No	CNES
BWP	Batteries	Off the Shelf	Direct use	No	CNES

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ASIC board which development at LAL is finished. Production of several boards has started. They should be delivered early 2012 for testing at LAL.

Note about ASIC acceptance plan: A few numbers of this test ASICs has already been packaged. 70% of them are working properly according to the design.

4. EC-ASIC BOARD

The design is on going for the EC-ASIC board. This design is the most critical of the EC UNIT, since the board includes the ASIC, the passive components and the connectors.

This board contains the first level of signal processing. There should be 8 such boards, each hosting 8 ASICs. These boards are connected to the EC-Front panel and to the PDM board.

The PCB will be produced by the industry. These boards will be tested at LAL, connectors, ASIC Packaging.

The development plan is foreseen as follow:

- A Proto PCB will be produce and be validated (electronic test) with the TEST-EC-ASIC board, which will be developed at LAL (beginning of 2011).
- The flight models will be produced.

5.3.2.4 MAPMT Procurement

Development assessment

The MAPMT component is designed and manufactured by Transnuclear Company.

MAPMT UFFO models have already been validated in test benches at APC and Riken as well as in the UFFO Polar qualification chamber (in MAPMT) as many as required for EUSO-BALLOON.

These photo detectors have to be produced for EUSO-BALLOON. The MAPMT flight models will be directly produced and used.

Using the filter is a high precision task requiring to align the filter with the photochannel with a 0.1 mm and that the glue thickness has to be controlled in a few tens micron with nominal thickness of 100 micron and position is controlled in 0.1 micron.

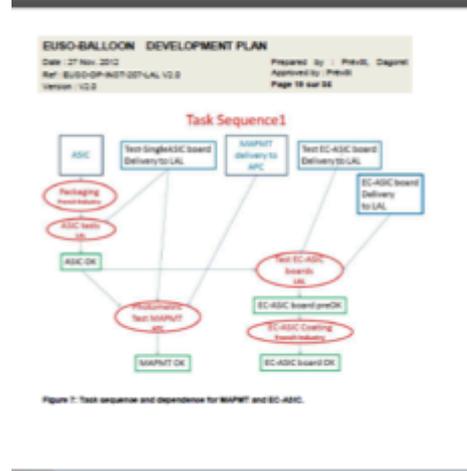
The Riken also provides the filter and is in charge of this going.

Acceptance tests

Preliminary acceptance and validation Tests will be done in Riken.

Performance tests and measurements will be done at APC. These measurements will allow writing the MAPMT according their performance, associating together set of four MAPMT having a similar gain to be extremes of the same EC unit.

These tests on the MAPMT can be done using the TEST-EC-ASIC board under development at LAL, and using an input signal induced by the photons generated by a LED illuminating uniformly the MAPMT photocathode.



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5.3.3 EC UNIT TASKS SEQUENCES AND VALIDATION PLAN

The sequence of tasks to perform going from the production of the components to the validation of the component is shown in Figures 7 and 8.

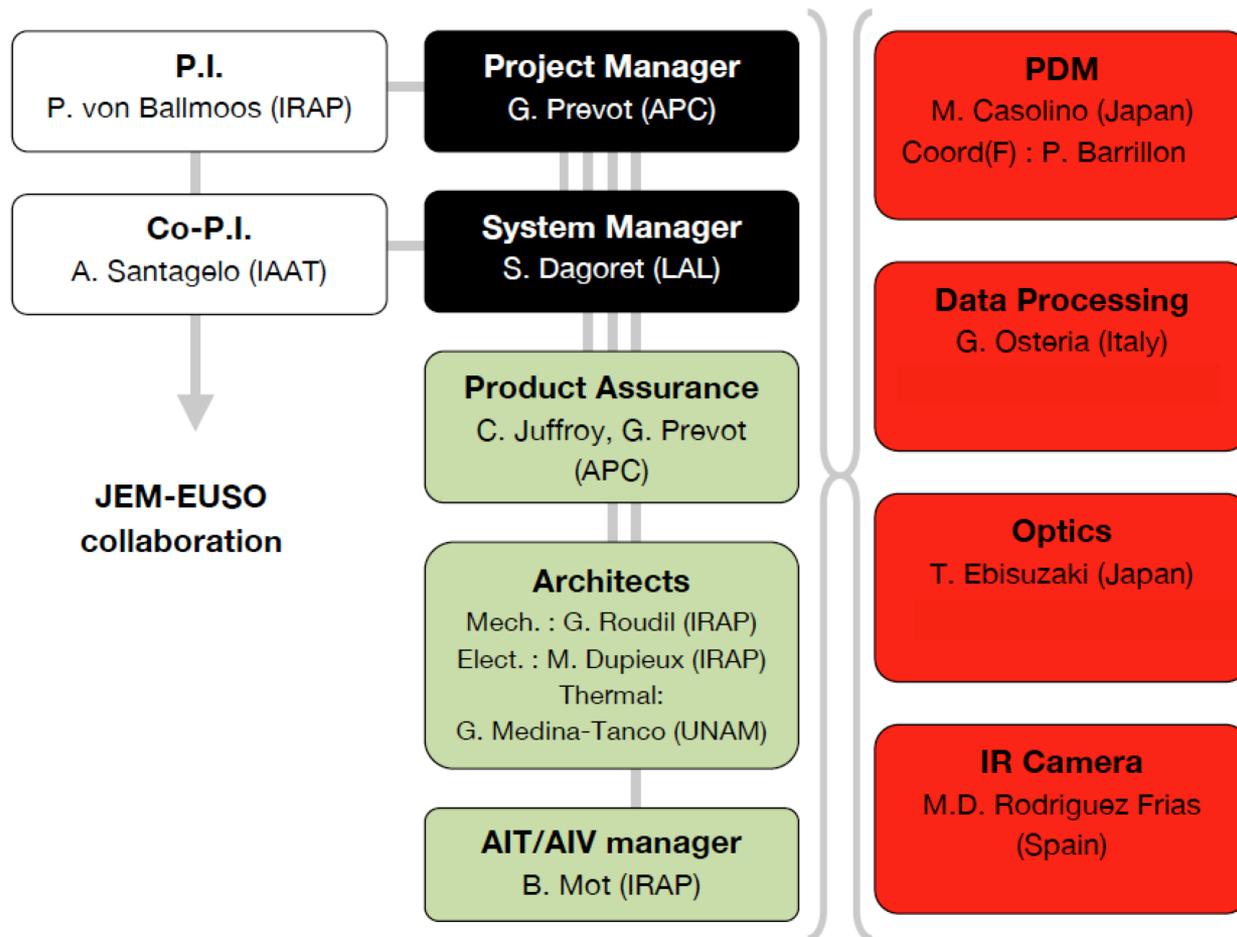
The series of tasks are specified in the Table 2, ordered by their sequence order (the later means the tests of the same task number do not depend on each other).

Table 2: tasks on the various components of the EC Unit

Sequence of tasks	Component	Test board	Test bench	Operation	Who does	When
18	Packaged ASIC	TEST-SingleASIC Board	ENRIF/INF	DAQ Reference	LAL	after packaging
19	16 HV test + Switches and MAPMT	Dynastore	ENRIF/INF	DAQ	APC	Received from Philips
20	Single MAPMT	TEST-SingleASIC Board	photometria	PMAT performance + HV	APC	Received from Riken
21	EC-ASIC BOARD	TEST-EC-ASIC Board	ENRIF/INF	DAQ Reference	LAL	PCB received from industry
3	EC-Front UFFO BOARD	TEST-EC-ASIC Board	photometria	Light calibration	APC	EC-Front UFFO from assembly industry
4	EC-Front UFFO BOARD + EC-ASIC BOARD	TEST-EC-ASIC Board	photometria	DAQ Reference	APC	EC-Front UFFO from assembly industry



Etablissement de la note d'organisation

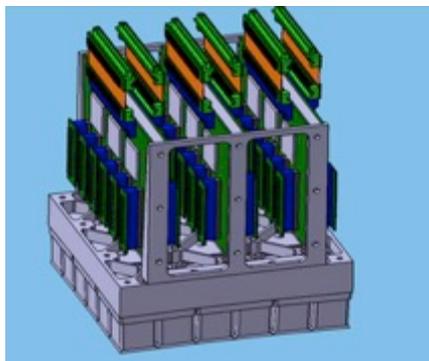
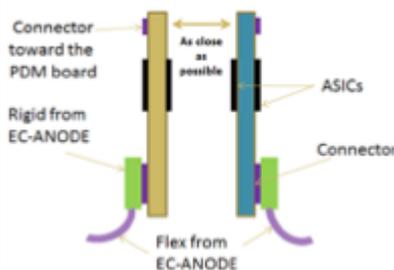
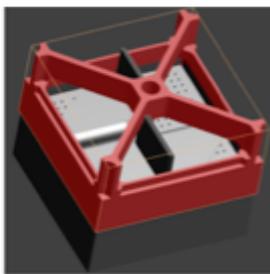
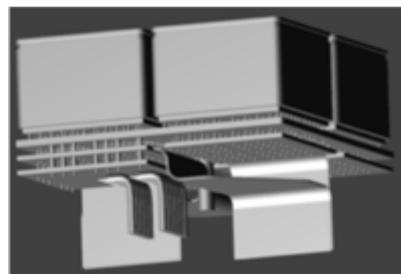
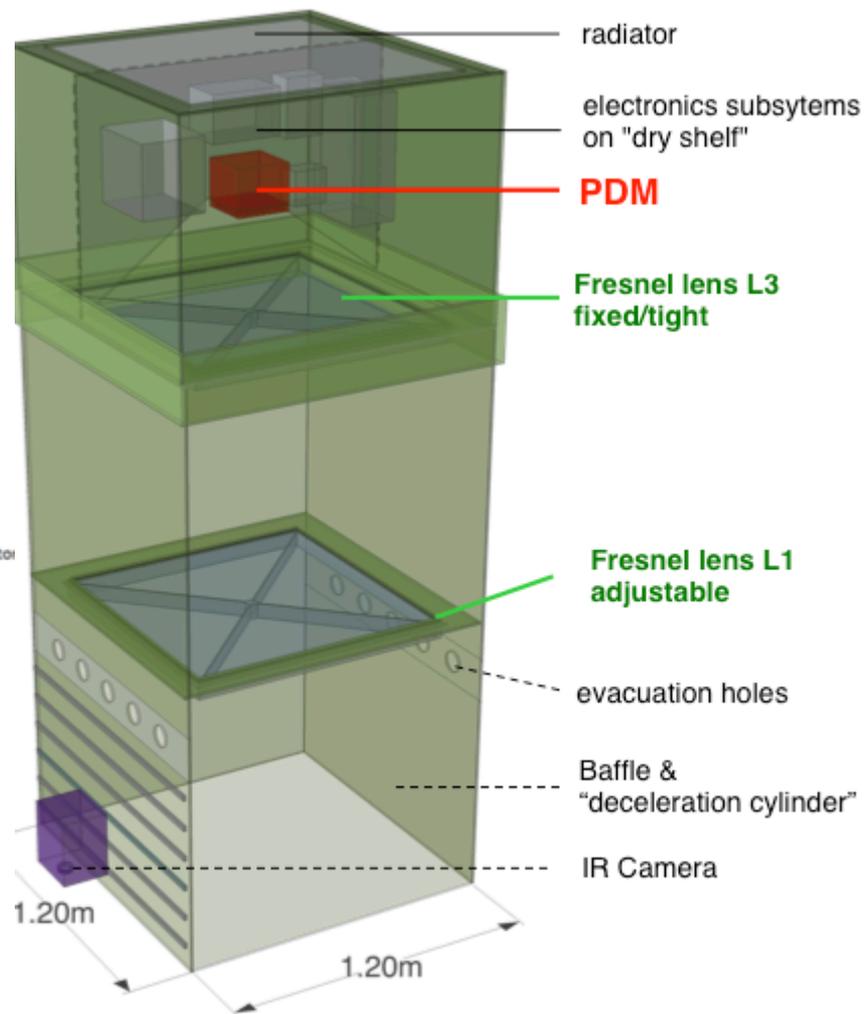
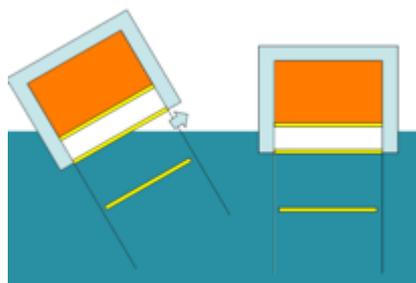
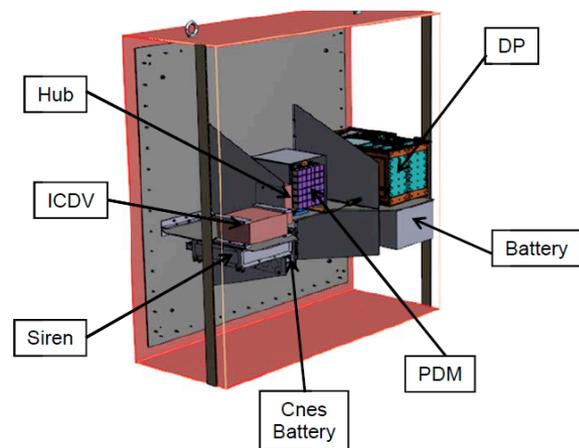


Difficultés projet :

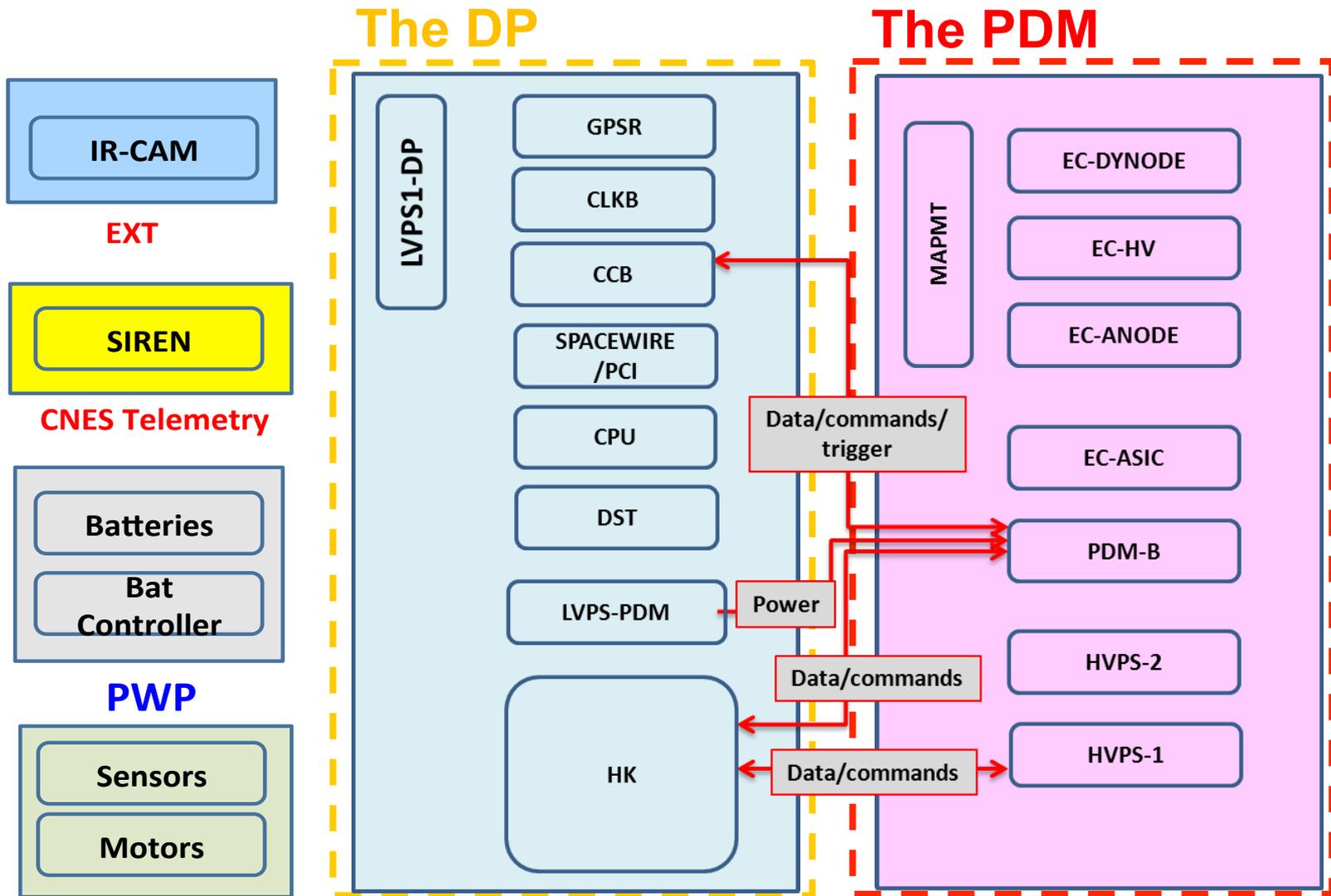
Nombreuses équipes sur le projet -> nombreuses I/F

- découpe par tâches PBS
- téléconférences spécifiques courtes (hebdomadaires) & réunions physiques collaboration (bimestrielles)
- Comptes rendus, documentation, revues nous ont aidé à nous structurer.

EUSO-Balloon: finalisation du design (documenté dans docs architectures)



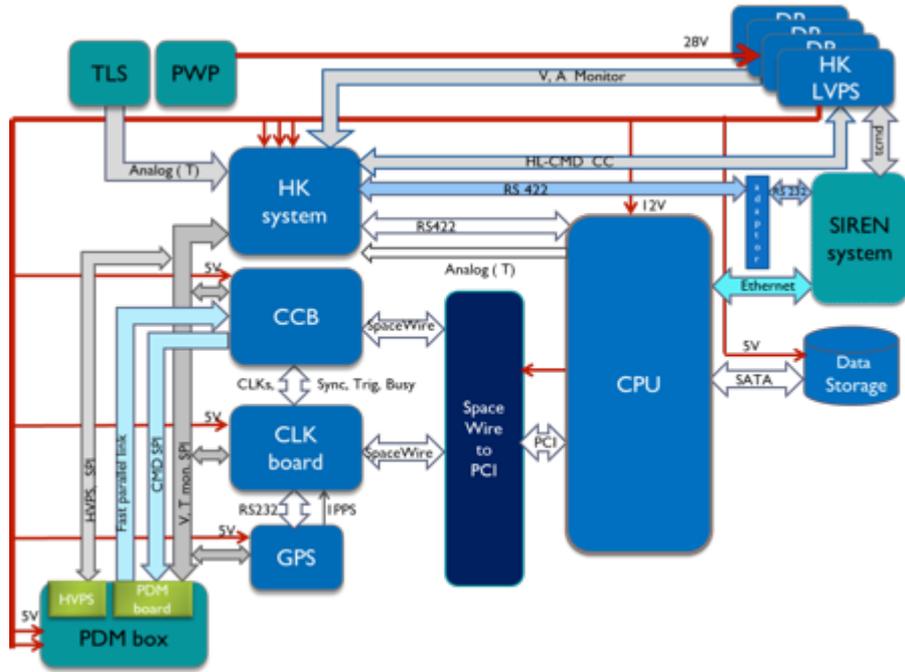
Formalisation de la structure détecteur



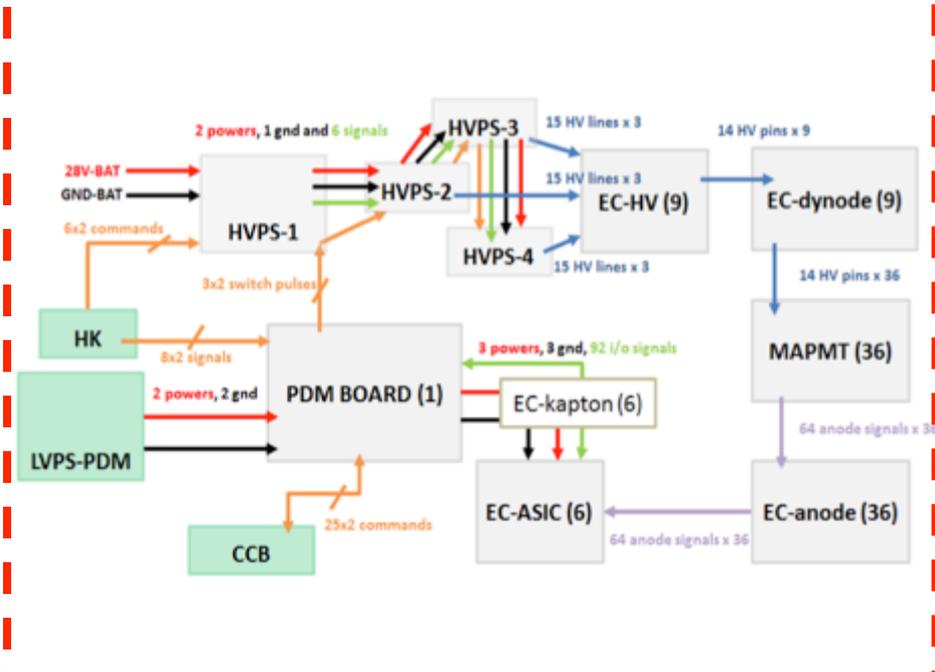
Le PDM détecte les photons UV issus des lentilles, digitalise les données et réalise le premier niveau de trigger. La chaîne électronique est constituée du DP qui réalise le second niveau de trigger, la synchronisation, l'acquisition et le stockage des données ainsi que la télémétrie.



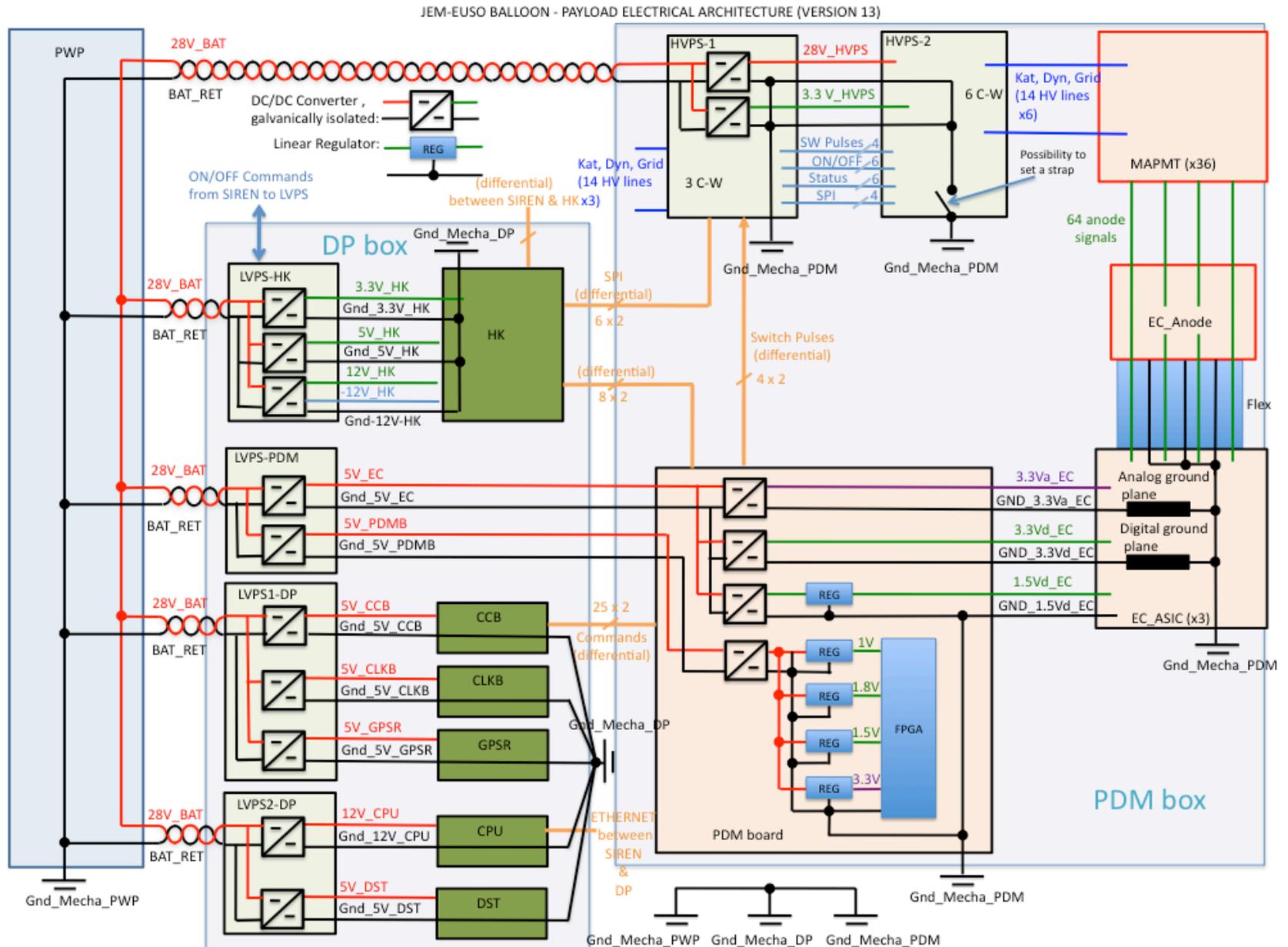
The DP



The PDM



Définition d'une architecture électrique (après revues internes et externes)



Liste des câbles I/F : spécifications et responsables



N°	Connection A/B	Shielding	Equipment	Connector Marking	Connector Reference	Shielding Connection to Cover	Shielding Connection to Cover	Connector Reference	Connector Marking	Equipment	Function	Remark	Who provide	Status	length
				A				B							
1	INSTRUMENT-PWP/LVPS1-DP	NO	PWP	PW-01M	DB 9M			DB 9M	LVDP1-01M	LVPS1-DP	PRIMARY POWER	TWISTED PAIRS	UNAM	OK	50 cm
2	INSTRUMENT-PWP/LVPS2-DP	NO	PWP	PW-02M	DB 9M			DB 9M	LVPD2-01M	LVPS2-DP	PRIMARY POWER	TWISTED PAIRS	UNAM	OK	50 cm
3	INSTRUMENT-PWP/LVPS-PDM	NO	PWP	PW-03M	DB 9M			DB 9M	LVPD-01M	LVPS-PDM	PRIMARY POWER	TWISTED PAIRS	UNAM	OK	50 cm
4	INSTRUMENT-PWP/LVPS-HK	NO	PWP	PW-04M	DB 9M			DB 9M	LVHK-01M	LVPS-HK	PRIMARY POWER	TWISTED PAIRS	UNAM	OK	50 cm
5	INSTRUMENT-PWP/HVPS-1	NO	PWP	PW-05M	DB 9M			DB 9M	HV1-03M	HVPS-1	PRIMARY POWER	TWISTED PAIRS	IRAP	OK	50 cm
6	LVPS1-DP/HK	NO	LVPS1-DP	LVDP1-02M	DB 37M			DB 37M	HK-05M	HK	SUPPLIES MONITORING		UNAM	OK	50 cm
7	LVPS1-DP/GPSR	NO	LVPS1-DP	LVDP1-03M	DB 9M			DB 9M	GPS-02M	GPSR	SECONDARY POWER	TWISTED PAIRS	INFN	OK	50 cm
8	LVPS1-DP/CLKB	NO	LVPS1-DP	LVDP1-04M	DB 9M			DB 9F	CLK-01F	CLKB	SECONDARY POWER		INFN	OK	50 cm
9	LVPS1-DP/CCB	NO	LVPS1-DP	LVDP1-05M	DB 9M			µD 9F	CCB-01F	CCB	SECONDARY POWER	TWISTED PAIRS	IAAT	OK	50 cm
10	LVPS2-DP/HK	NO	LVPS2-DP	LVDP2-02M	DB 25M			DB 25M	HK-04M	HK	SUPPLIES MONITORING		UNAM	OK	50 cm
11	LVPS2-DP/CPU	NO	LVPS2-DP	LVDP2-03M	DB 15M			DB 15F	CPU-05F	CPU	SECONDARY POWER	TWISTED PAIRS	INFN	OK	50 cm
12	LVPS-PDM/HK	NO	LVPS-PDM	LVPD-02M	DB 25M			DB 25M	HK-01M	HK	SUPPLIES MONITORING		UNAM	OK	
13	LVPS-PDM/PDMB	YES	LVPS-PDM	LVPD-03M	DB 9M	YES @ 90°	YES @ 90°	µD 9M	PDM-01M	PDMB	SECONDARY POWER	TWISTED PAIRS	UNAM	OK	
14	LVPS-HK/HK	NO	LVPS-HK	LVHK-02M	DB 9M			DB 9M	HK-02M	HK	SUPPLIES MONITORING		UNAM	OK	
15	LVPS-HK/HK	NO	LVPS-HK	LVHK-03M	DB 9M			DB 9M	HK-11M	HK	SECONDARY POWER	TWISTED PAIRS	UNAM	OK	
16	LVPS-HK/SIREN	NO	LVPS-HK	LVHK-04M	DB 15M			DB 44M	SIR_TOR	SIREN	ON/OFF COMMMANDS		UNAM	OK	
17	HK/LENSES	YES	HK	HK-03M	DB 25M	YES @ 90°	NO		CAPTEURS T	LENSES	TM		UNAM	OK	
18	HK/PDMB	YES	HK	HK-06M	DB 25M	YES @ 90°	YES @ 90°	µD 25M	PDM-02M	PDMB	LVDS	TWISTED PAIRS	UNAM	OK	
19	HK/RS232-RS422 ADAPTOR	YES	HK	HK-07M	DB 9M	YES @ 90°	YES @ 90°	DB 9F	ADAP-02F	RS232/RS422 ADAPTO	RS422	TWISTED PAIRS	UNAM	OK	
20	HK/CPU	YES	HK	HK-08M	DB 9M	YES @ 90°	YES @ 90°	DB 9F	CPU-04F	CPU	RS422	TWISTED PAIRS	INFN	OK	50 cm
21	HK/CCB	YES	HK	HK-09M	DB 25M	YES @ 90°	YES @ 90°	µD 25M	CCB-02M	CCB	LVDS	TWISTED PAIRS	IAAT	OK	45 cm (max)
22	HK/CLKB	YES	HK	HK-10M	DB 25M	YES @ 90°	YES @ 90°	DB 25F	CLK-02F	CLKB	LVDS	TWISTED PAIRS	INFN	OK	45 cm (max)
23	HK/HVPS-1	YES	HK	HK-12M	DB 15M	YES @ 90°	YES @ 90°	DB 15M	HV1-01M	HVPS-1	LVDS	TWISTED PAIRS	UNAM	OK	45 cm (max)
24	HK/GPSR	YES	HK	HK-13M	DB 15M	YES @ 90°	YES @ 90°	DB 15M	GPS-01M	GPSR	LVDS	TWISTED PAIRS	INFN	OK	45 cm (max)
25	SIREN/RS232-RS422 ADAPTOR	YES	SIREN	SIR_SY/AS	µD 62M	YES @ 90°	YES @ 90°	DB 9 F	ADAP-01F	RS232/RS422 ADAPTO	RS232		UNAM	OK	
26	SIREN/CPU	YES	SIREN	SIR-Ethernet	RJ45_M	YES @ 90°	YES @ 90°	RJ45 M	CPU-06M	CPU	ETHERNET		INFN	OK	
27	HVPS-1/PDMB	YES	HVPS-1	HV1-02M	µD 9M	YES @ 90°	YES @ 90°	µD 9M	PDM-03M	PDMB	HV GAIN PULSES - LVDS	TWISTED PAIRS	APC	OK	
28	HVPS-1/HVPS-2	YES	HVPS-1	HV1-04F	DB 25F	YES @ 90°	YES @ 90°	DB 25M	HV2-01M	HVPS-2	HVPS-1 HVPS-2		APC	OK	
29	PDMB/CCB	YES	PDMB	PDM-04M	µD 51M	YES @ 90°	YES @ 90°	µD 51M	CCB-05M	CCB	LVDS	TWISTED PAIRS	IAAT	OK	
30	CCB/CPU	YES	CCB	CCB-03M	µD 9M	YES @ 90°	YES @ 90°	µD 9M	CPU-02M	CPU	Space-Wire2		IAAT	OK	
31	CCB/CLKB	YES	CCB	CCB-04M	µD 15M	YES @ 90°	YES @ 90°	µD 15M	CLK-06M	CLKB	DIFFERENTIAL CLOCKS	TWISTED PAIRS	IAAT	OK	
32	CLKB/CPU	YES	CLKB	CLK-03F	µD 9M	YES @ 90°	YES @ 90°	µD 9M	CPU-01M	CPU	Space-Wire1		INFN	OK	50 cm
33	CLKB/GPSR	YES	CLKB	CLK-05M	µD 15M	YES @ 90°	YES @ 90°	µD 15M	GPS-03M	GPSR	DIFFERENTIAL SERIAL I/F	TWISTED PAIRS	INFN	OK	45 cm (max)
34	GPSR/GPS-ANTENNA	COAX	GPRS	GPS-04M	SMA M			SMA M	Antenna-GPS-M	GPS2-ANTENNA	GPS RF SIGNAL		INFN	OK	5 m

Rédaction commune de 35 documents pour les revues CNES CDR (revue de design) et RAV (revue de vol) :

Documents de spécifications (instrument et mission) et de définition (instrument et logiciel de vol)

Docs d'architectures (électrique, mécanique, thermique)

Documents d'interfaces (électrique, mécanique)

Plan de développement

Plan d'assemblage, d'intégration et de tests PAIE

Rapports de tests

Matrices de conformités (à l'assurance produit CNES et aux spécifications)

Document d'analyse de risques

Planning MS Project (250 lignes, MAJ à chaque revue)

avec l'aide de la cellule qualité APC et du CNES

reference tag	Title	version tag	doc file	pdf file
EU30-CN- INST-261-LAL	EU30 Balloon Organization Note	2.0	 Organization Note	 Organization Note
EU30-CP- INST-264-LAL	EU30 Balloon Instrument Definition	2.0	 Instrument Definition	 Instrument Definition
EU30-TS- INST-266-LAL	EU30 Balloon Technical Specifications	2.0	 Technical Specifications	 Technical Specifications
EU30-CP- INST-267-LAL	EU30 Balloon Development Plan	2.0	 Development Plan	 Development Plan
EU30-RI- INST-269-LAL	EU30 Balloon Conformity Matrix	2.0	 Conformity Matrix	 Conformity Matrix
EU30-TSP- INST-268-LAL	EU30 Balloon Technical specification for CPU software	1.0	 CPU software	 CPU software
EU30-AI- INST-261-LAL	EU30 Balloon Assembly Integration and Test plan	1.0	 AIT plan	 AIT plan
EU30-MS- INST-466-RLUP	EU30 Balloon Mission specifications	2.0	 Mission specifications	 Mission specifications
EU30-MI- INST-466-RLUP	EU30 Balloon Mechanical Architecture	1.0	 Mechanical Architecture	 Mechanical Architecture
EU30-MI- INST-466-RLUP	Mechanical Interface Control Document	1.0	 Mechanical ICD	 Mechanical ICD
EU30-EC- INST-467-RLUP	EU30 Balloon Electrical Interface Document	1.0	 Electrical ICD	 Electrical ICD
EU30-TS- INST-468-RLUP	EU30 Balloon Thermal Analysis and impact on mechanical architecture	1.0	 Thermal Analysis	 Thermal Analysis
EU30-RI- INST-464-RLUP	EU30 Balloon Risk Analysis	2.0	 Risk analysis	 Risk analysis
EU30-EA- INST-461-4PC	EU30 Balloon Electrical architecture	1.0	 Electrical Architecture	 Electrical Architecture
EU30-VM- INST-461-4PC	EU30 Balloon Verification matrix to the technical requirements	1.0	 Verification Matrix	 Verification Matrix
EU30-CN- INST-461-4PC	EU30 Balloon Calibration Note	1.0	 Calibration Note	 Calibration Note
EU30-PRR- INST-461-4PC	EU30 Balloon Answers to the PRR Steering Committee Report	1.0	 Answers PRR	 Answers PRR
EU30-SCH- INST-261-4PC	EU30 Balloon	1.0		

Spécifications techniques

EUSO-BALLOON TECHNICAL SPECIFICATION DOCUMENT
 Date: 27 Nov 2012 Prepared by: A. Sarajedini
 Ref: EUSO-BALLOON-TECH-001-001-001 Approved by: IMB-UK
 Version: 1.0.0 Page 41 of 61

The Camera sub-system mainly consists of an infrared Camera and of a Filter wheel. The latter is at the edge optical and is being considered for acquisition rights.

4. INSTRUMENT SPECIFICATIONS AND REQUIREMENTS

The EUSO Balloon instrument shall be the proof of the JEM-EUSO observational concept and shall measure the diffuse UV photon flux observed in the field of view during night and during twilight. The operational mode of the instrument, described in detail in the Mission Definition Document, are summarized as follows according to category A, B, and C:

A) In-air technology demonstrator

- Full scale end-to-end test of JEM-EUSO proof of concept and technique
- Operations of components like the PCM, ADCs, FEE, Trigger, HV switches, To board) space environment, increase of the TMA level of several JEM-EUSO components
- Resilience of signals in a large dynamic range

B) Real data and background

- Experimentation confirmation of the effective UV background below 400 nm
- Acquisition of JEM-EUSO type data
- Robot trigger algorithms with real data

C) Precursor studies

- UV detection of EAS by looking down from the edge of space
- Detection of low reduced events from space

4.1 Functional Requirements

4.1.1 Background Imaging

The instrument shall image the UV sky background in the bandwidth used by the JEM-EUSO camera observational technique.

The background includes star light, airglow, light from artificial sources.

4.1.2 Detection of EAS

The instrument shall trigger, detect and image EAS with energy above 10^8 eV that

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might develop in the field of view.

4.1.3 Technology Demonstrator

All key components and the entire sub-systems shall be tested according to the configuration scenarios for the JEM-EUSO mission.

This is needed to test the JEM-EUSO detection technique.

These goals allow the parameters for the EUSO balloon mission, including the parameters for the Instrument subsystems and components.

4.2 Performance Requirements

4.2.1 Spectral Range

The spectral range shall cover the bandwidth (360-430 nm)

This is determined by the spectral distribution of the cosmic lines of nitrogen fluorescent emission in Earth atmosphere.

4.2.2 Signal Sensitivity for low illumination

The instrument shall work in single photo-electron (SPE) mode.

Single photo-electron mode, often improperly called 'single photon counting' mode, allows the binomial reconstruction of the EAS track point per point in a signal limited photon-counting equipment. It is one of the two modes of the JEM-EUSO observational technique.

4.2.3 Signal Gain

The instrument shall provide a pulse of 10P electrons from one photoelectron (Gain = 10P) when in slower or background mode.

This is required by constraints on the intensity of the signal (and therefore on the PMT gain).

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4.2.4 Dynamic range

From 1 to 10^7

The instrument shall operate in strong light mode. In this case the gain is automatically reduced and the mode is switched to signal integration.

4.2.5 Signal Sensitivity for strong light events

The instrument shall work in charge integration mode.

The charge integration mode will be used for particularly intense signals, where the photon-counting mode might go into saturation (characterized by extremely bright events). It is one of the two modes of the JEM-EUSO observational technique.

4.2.6 Pixel size in the Field of View

$0.28^\circ \times 0.28^\circ$ corresponding to a pixel on ground of $176 \text{ m} \times 176 \text{ m}$

Determined by the combination of FOV and focal surface pixel size. Note that the focal surface is the PCM prototype designed for the JEM-EUSO mission.

4.2.7 Full-frame read-out time

$10^\circ \times 10^\circ$

Required by trade-off towards a JEM-EUSO the prototype (see feasibility) and by the possibility of detecting an EAS.

4.2.8 Time Resolution

Smaller than 30 ns for each signal of the ASIC, 2.0 ns for events

The required values allow the binomial reconstruction of the EAS tracks. They have been optimized in simulation studies of the JEM-EUSO observational technique.

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4.3 Environmental and Safety Requirements

4.3.1 Vertical acceleration

The instrument shall withstand vertical acceleration equal to $10g$.

Required by balloon operations.

4.3.2 Lateral acceleration and roll acceleration

The instrument shall withstand acceleration equal to $1g$ by frequency and by 40° .

Required by balloon operations.

4.3.3 Extreme outdoor temperature

The instrument has to withstand an outdoor temperature as low as -60°C .

Required by environmental conditions. Remark: Outdoor temperature when instrument is operated can be as low as -60°C .

4.3.4 Instrument Water Tightness

Must be waterproof

Following the launch site of the payload, operations might end in water. Necessity of recovery of the instrument for other technical and/or ground-testing.

4.3.5 Operating pressure

The instrument has to support pressures between 1100 and 1170 hPa, the critical pressure for absolute sensitivity of air being 1170 hPa.

Required by balloon operations.

4.3.6 Operating temperature limit

The PCM and SP shall be operated at a temperature in the range -60°C - $+60^\circ\text{C}$.

The image displays a grid of 16 pages from the EUSO-BALLOON Technical Specification Document. Each page contains detailed technical information, including:

- Page 41:** Introduction and overview of the instrument's purpose and operational modes.
- Page 42:** Functional Requirements, including background imaging and signal detection.
- Page 43:** Performance Requirements, detailing spectral range, signal sensitivity, and signal gain.
- Page 44:** Environmental and Safety Requirements, covering vertical and lateral acceleration, temperature, and water tightness.
- Page 45:** Operating pressure and temperature limits.
- Page 46:** Additional performance and environmental specifications.
- Page 47:** Further details on the instrument's capabilities and requirements.
- Page 48:** Information on the instrument's design and components.
- Page 49:** Details on the instrument's operational modes and data handling.
- Page 50:** Further technical specifications and requirements.
- Page 51:** Information on the instrument's safety and environmental resilience.
- Page 52:** Additional performance and environmental specifications.
- Page 53:** Further details on the instrument's capabilities and requirements.
- Page 54:** Information on the instrument's design and components.
- Page 55:** Details on the instrument's operational modes and data handling.
- Page 56:** Further technical specifications and requirements.
- Page 57:** Information on the instrument's safety and environmental resilience.
- Page 58:** Additional performance and environmental specifications.
- Page 59:** Further details on the instrument's capabilities and requirements.
- Page 60:** Information on the instrument's design and components.
- Page 61:** Details on the instrument's operational modes and data handling.

Documents d'analyse des risques



EVENT		Risk Factor	Risk Scenario		Risk		
ID	EVENT		ID	Name	ID	cause	mitigation
RD	Unsuccessful development	PROCUREMENT	RD	Unable to reach program objectives			
			RD1	Key elements not available	RD1.1	FRESNEL lenses not available at due time	plenty of contingency time is already budgeted by TOSHIBA
					RD1.2		resist for TA.
		RD1.3				are needed.	
		DEVELOPMENT	RD2	Development of key system elements not successful	RD2.1	Delay in the EC integration	ASIC yield is around 70%. Packaging of new ASICs can be done if the yield is found too low.
					RD2.2	Delay of HV design (occurs after EC and PDM electronics)	Mockup + prototype (PFM) product company in charge of it. The sub-CNES expert is following the dev.
					RD2.3	Phone Booth / Instrument design not adequate	Mitigation by use of a commercial this is TBC, since it would imply Trade off with other technical risks sufficient time (factor 4) for redesign review to freeze the design taking instrument.
		SCHEDULE	RD3	program exceeds schedule	RD3.1	NOSYCA not qualified in due time	Is now sufficiently close to the de
		MANAGEMENT	RD4	program exceeds schedule	RD3.2	Launch site logistics not ready in due time	Kinana is already perfectly establish
					RD4.1	Very large collaboration with many actors involved in various subsystems, risk of inadequate management	mitigated with efficient organization B

approvisionnementnements

intégration

ID	Risk Cause	Likelihood 1 (<0.01%) to 5 (=1)	Severity 1 (negligible) to 4 (critical)				Risk Index			
			Science performance	Instrument Performance	Safety	Schedule / Cost	Science performance	Instrument Performance	Safety	Schedule / Cost
RD1.1	FRESNEL lenses not available at due time	2				4				8
RD1.2	PMT's not available at due time +	1				4				4
RD1.3	ASIC delivery (ASIC production has unknown yield)	1				2				2
RD2.1	Delay in the EC integration	2				4				8
RD2.2	Delay of HV design (occurs after EC and PDM electronics)	0				0				0
RD2.3	Phone Booth / Instrument design not adequate	1				4				4
RD3.1	NOSYCA not qualified in due time yield)	1				4				4
RD3.2	Launch site logistics not ready in due time	1				4				4
RD4.1	Very large collaboration, many actors and subsystems, inadequate management	2				4				8

Table 2-1: Risk factors, scenarios and mitigations for the development phase

Risk scenarios: Implementation phase

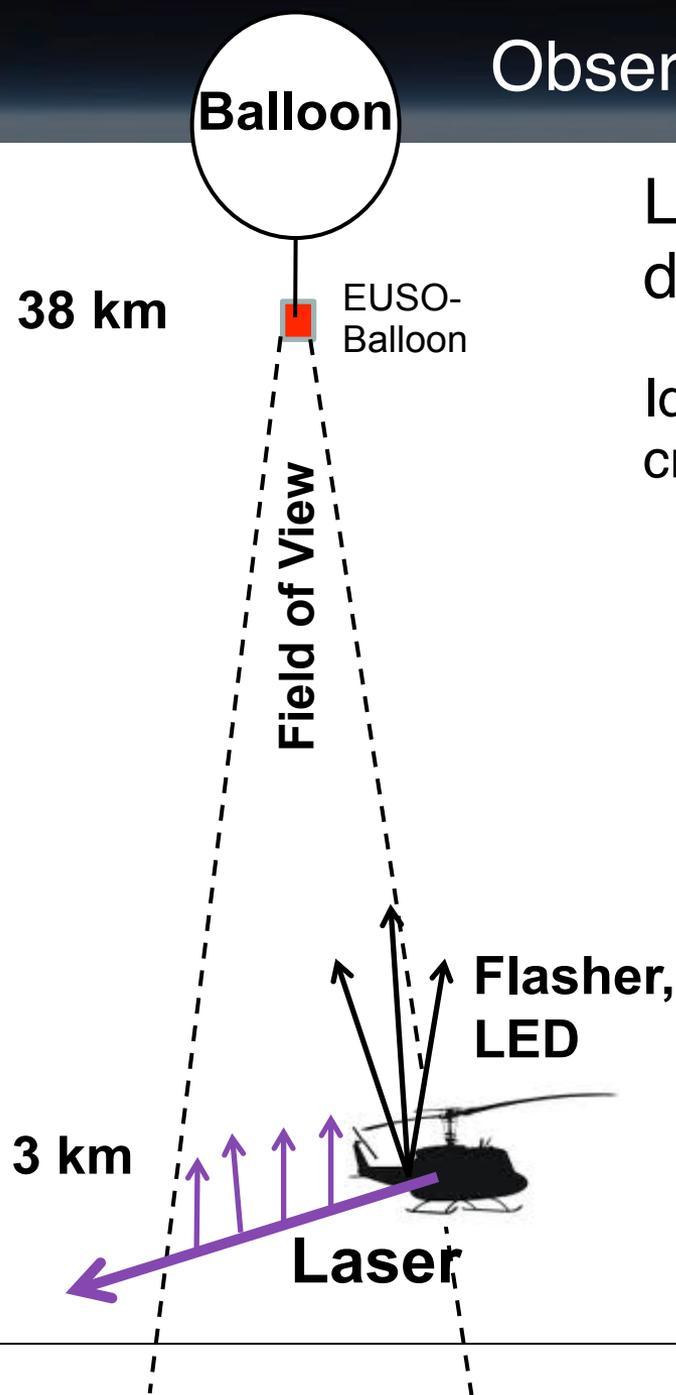
EVENT		Risk Factor	Risk Scenario		Risk		
ID	EVENT		ID	Name	ID	cause	mitigation
RI	Unsuccessful implementation	ELECTRONICS	RI	Unable to implement payload.			
			RD1	Failure to implement subsystem	RI1.1	Failure in complex MAPMT pins soldering	Mockup and EC proto to train, mature subcontractor & help from CNES
					RI1.2	EC board and integration design not satisfying the requirements	EC proto will verify that the design meets the requirements. Phase B review will evaluate this point.
					RI1.3	EC insulation insufficient on dense printed circuit board (failure due to short circuit between ground' and ...)	a) we have made the choice of an appropriate CAD design, b) all the HV
					RI1.4	Failure of HV Crocodile-Walton: no m...	
		RI1.5			Failure of HV Switches: cannot switc...	off manually in case of intense light.	
		RI1.6	Failure of HV Switches: cannot protect MAPMT	a) this will be simulated with the prototype b) stay at high gain & switch-off manually in case of intense light.			
		RI1.7	Interface Inconsistency between components.	System manager for both PDM and DP in the organization whose role is to managing interfaces. Design review foreseen to verify this issue.			
		MECHANICS	RD2	Failure of mechanical subsystem	RI2.1	Fresnel lenses not matched by platform mechanics	Spider or Lenses can be re-machined easily
					RI2.2	Fresnel lens(es) broken during integration	Lenses will be protected at any time, Protection removed for launch
					RI2.3	Fresnel lens(es) broken during flight	
		SYSTEM	RD3	program exceeds schedule	RI3.1	Instrument exceeds available mass envelop	
					RI3.2	Project exceeds available M/power resource envelop	Phase A to define tasks, organization and necessary manpower. Phase A review to assess this point.

développements

Lancement / vol

ID	Risk Cause	Likelihood 1 (<0.01%) to 5 (=1)	Severity 1 (negligible) to 4 (critical)				Risk Index			
			Science performance	Instrument Performance	Safety	Schedule / Cost	Science performance	Instrument Performance	Safety	Schedule / Cost
LAUNCH: BALLOON FAILURE										
RP1.1	Failure of balloon to reach float altitude	2	2	2		3	4	4		4
RP1.2	Failure of the balloon to hold for the mission required time	2	4	2		3	4	4		4
FIRE										
RP1.3	Over heat after landing	1	1	1		2	1	1		2
RP1.4	Over heat of damaged battery	1	1	2		2	1	2		2
RP1.5	Over heat of the instrument	1	2	3		2	2	3		2
RP1.6	Spark or Discharge	1	1	1		1	1	1		1
EXPLOSION										
RP1.7	Explosion of the explosive device due to improper design and/or operation.	1	3	3		3	3	3		3
RP1.8	Improper design of Pressure vessel may explode.	1	3	3		3	3	3		3
RP1.9	Internal short circuit may cause explosion of the battery.	1	4	4	2	4	4	4	2	2
FALLING PARTS										
RP1.10	Loose fasteners may be falling out from instruments.	1	1	1		3	1	1		3
RP1.11	Falling Component	1	1	3		3	1	3		3
RP1.12	Falling or Detachable sub-assemblies or units.	1	1	2		3	1	2		3

Table 2-2: Risk factors, scenarios and mitigations for the implementation phase



Les chances de détecter des RC au court d'un vol d'une nuit sont trop faibles...

Idée de nos collègues américains : pourquoi ne pas créer nos propres évènements ?

En utilisant un hélicoptère

Equipé d'un Laser et de LED pulsés

Volant sous le ballon au plafond

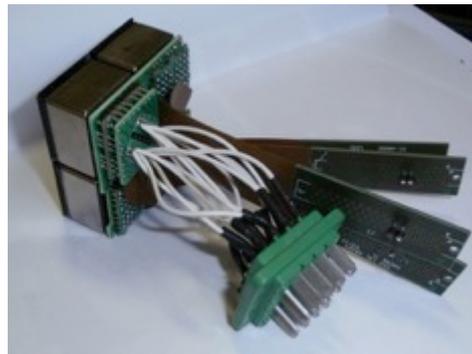
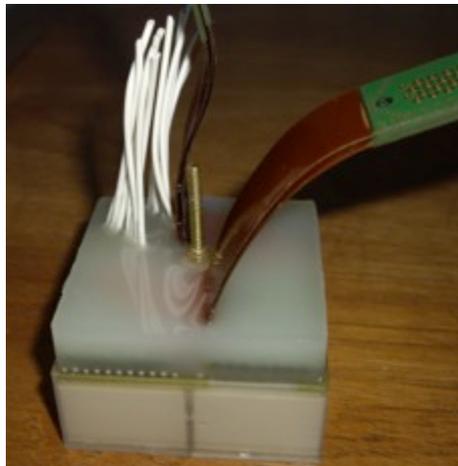
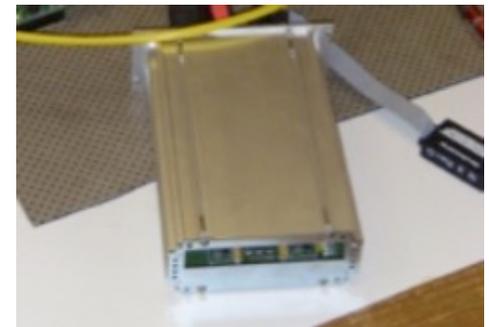
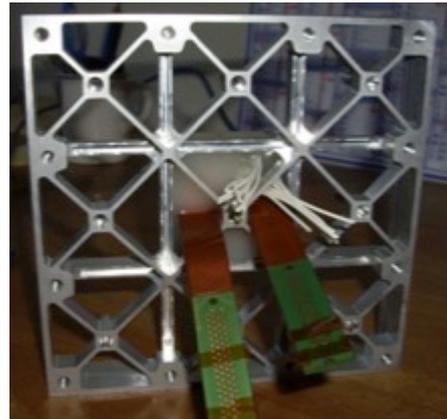
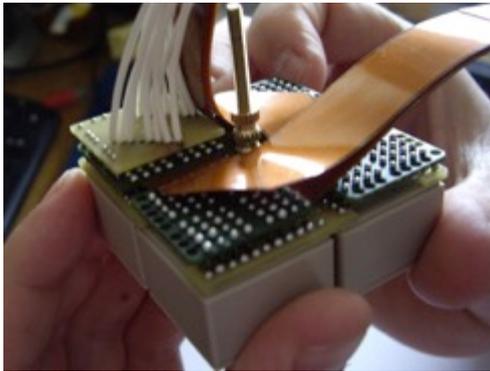
Les tirs laser et LED synchronisés avec l'acquisition de données (2 GPS)



Démarrage de la Phase B: réalisation des prototypes



De Juillet à Déc. 2012 : développement et tests des prototypes
Philo. PFM pr certains modèles // EM -> FM pour les + critiques



Les points clés EUSO-Ballon :



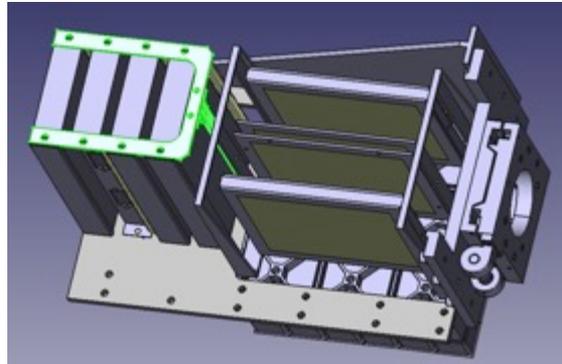
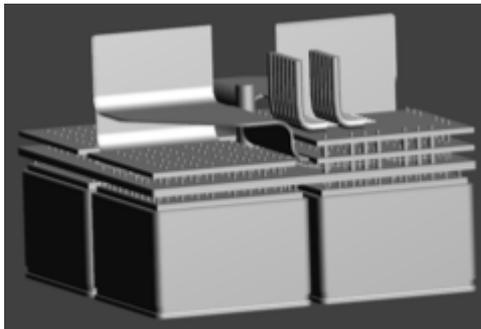
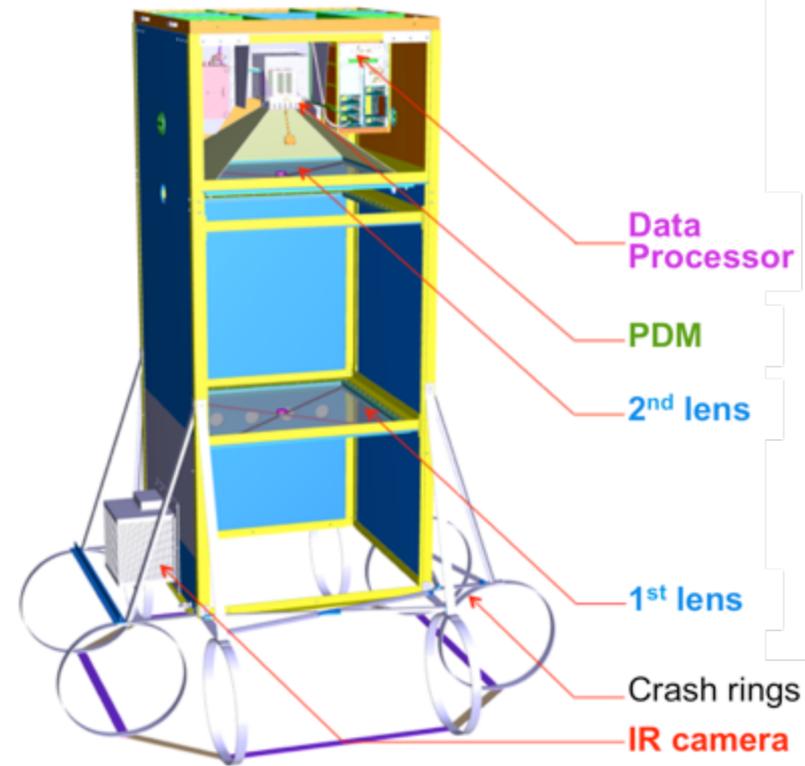
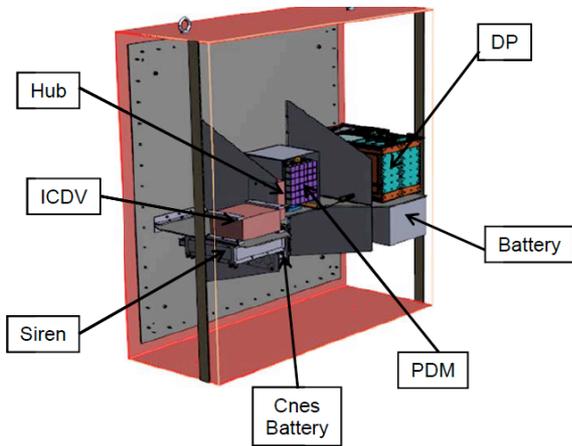
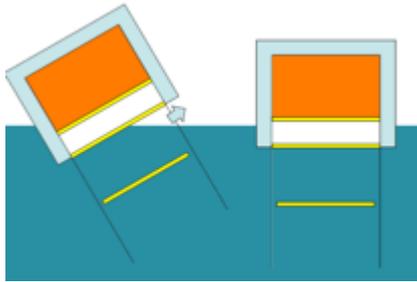
14 Sept. 2011 : *Phase A kick-off*



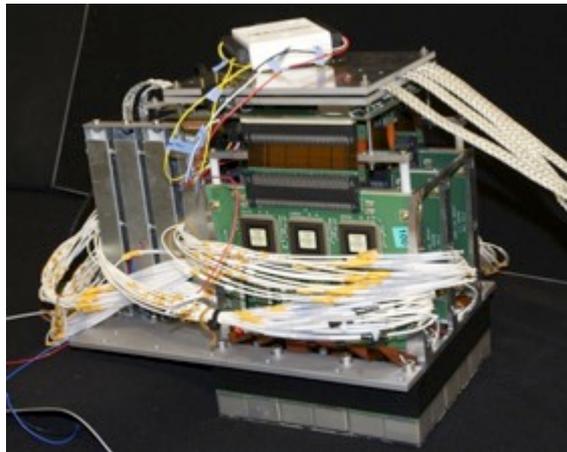
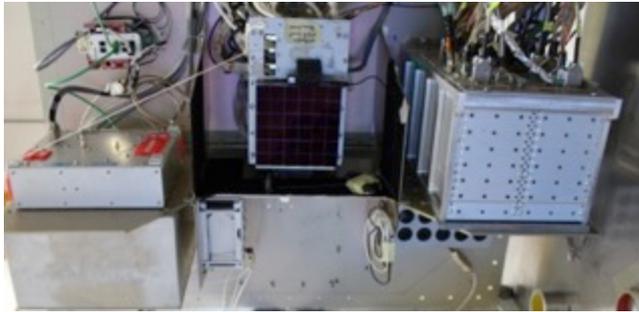
18 Dec. 2012 : *Critical Design Review* (pour passage en phase raccourcie C/D)

- CDR suivie d'une réunion de réponses aux 30 RID (*Review Item Discrepancy* = FEPS en français) + rédaction d'un document dédié de réponses aux RID.
- CDR suivie de MRR (MANUFACTURING READINESS REVIEW) pour tous les sous-systèmes début 2013.
- Feu vert pour le démarrage de la phase finale C/D en février 2013

EUSO-Balloon: du design (phase A)...



... à la réalisation des FM (durant la phase raccourcie C/D)



Phase C&D: production of the Flight Models

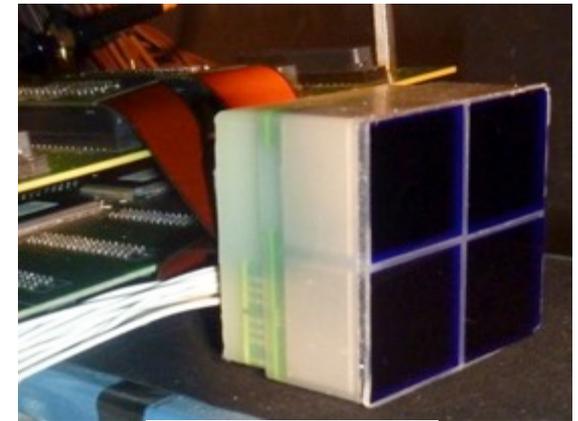
De février à octobre 2013 : Production des modèles FM (pour les non PFM) et des spares



6 FM EC-ASIC in mechanical structure



FM PDM board



FM EC unit



CPU, GPS, CLKb



CCB

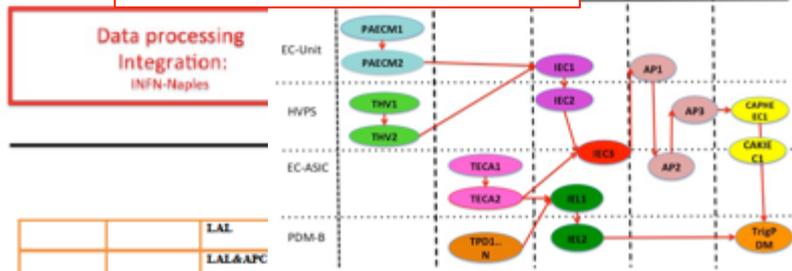
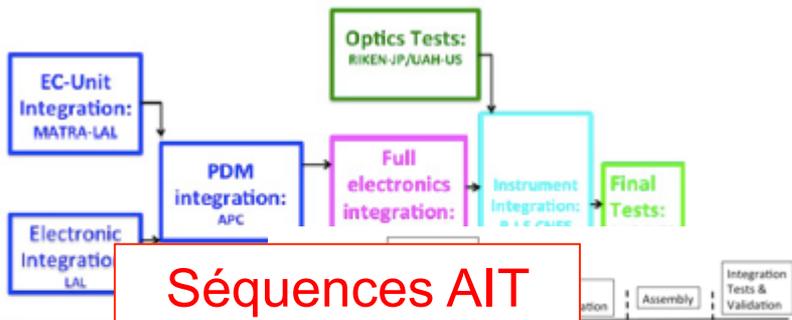


HK



LVPS's

Le PAIE (Plan d'Assemblage, d'Intégration et d'Essai) = 70 pages



Responsible	Task	Description	
LAL	LAL&APC		
LAL&Korea	IEL1 (pre-integration)	Test of EC-ASIC resident with PDM-B	
LAL&Korea & Naples	IEL2 (pre-integration)	Test of EC-ASIC and PDM-B resident with DP	
LAL	AP1 Assembly	Connecting 36 EC-Asic flex cables	
APC&LAL	CAPHE1 Calibration	Calibration of Photocathode channels of the ASICs	
APC&LAL	CAKIEC1 calibration	Calibration of the KI of the ASICs	
PDM-B	Korea	Korea	
	TPD1 (component-test)	Electrical mechanical compatibilities	
	Korea	TPD2 (component-test)	Power supply tests
	Korea	TPD3	ASIC configuration
		TPD4	Electrical tests
		TPD5	Electrical tests
		TPD6	DP (or CCB) interfaces
		TPD7	DP (or CCB) interfaces
		TPD8	DP (or CCB) interfaces
LAL&Korea	IEL1 (pre-integration)		
LAL&Korea & Naples	IEL2 (pre-integration)		
Korea	TrigPDM Validation		
Korea&APC	SWLag Validation		

4.2 CONSTITUTION OF THE AIT TEAMS

The instrument AIT teams are identified in the following list:

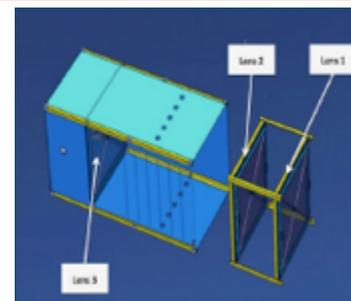
- RAIT of the instrument: B. Mot (IRAP)
- Mechanical AIT responsible: G. Roudil (IRAP)
- Electronics AIT responsible: M. Dupieux (IRAP)
- Optical AIT responsible: B. Mot (IRAP)
- AC... (IRAP)

Responsables

The subsystem AIT teams are identified in the following list:

- PDM AIT responsible: P. Barrillon/S Dagoret-Campagne (LAL)
- DP AIT responsible: G Osteria (INFN-Naples)

Procédures d'assemblages



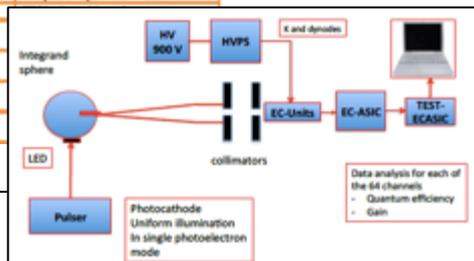
Description des tests

6.1.2.2.3 Tests of EC-ASIC

These tests are performed at LAL, once the EC-ASIC boards are received by cabled, with their connectors, the ASICs SPACIROC being soldered on the P...

- Power supplies delivering the functioning voltages to the test-board
- A computer running Labview programs allowing ASICs configuration and recording.
- A pulse generator to inject MAPMT like signals
- A multimeter to measure DC voltages
- A oscilloscope to look at analog and digital signals

6.1.2.2.3.1 Test TECA1



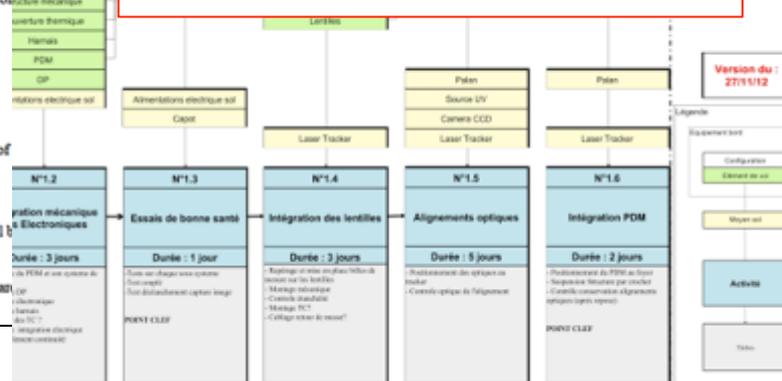
...ted visually to check the quality of the soldering of the 64 channels of the EC-Unit.

...performances

...ally tested. All its characteristics will be checked.

...s (slow control and probe register an...

Fiches de tâches AIT



Liste des tests



Test individuels:

Tri et sélection des MAPMTs et des ASICs

EC units (mesures gain & efficacité)

Performances cartes EC-ASICs

Communication carte FPGA

Tests HVPS (alimentation MAPMT, switches, protections)

Tests Basse Pression

Tests Température

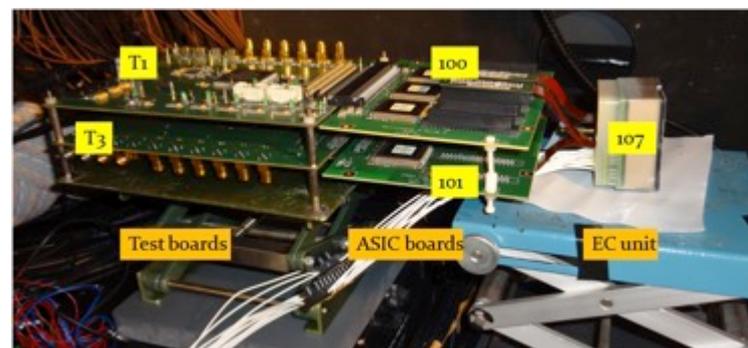
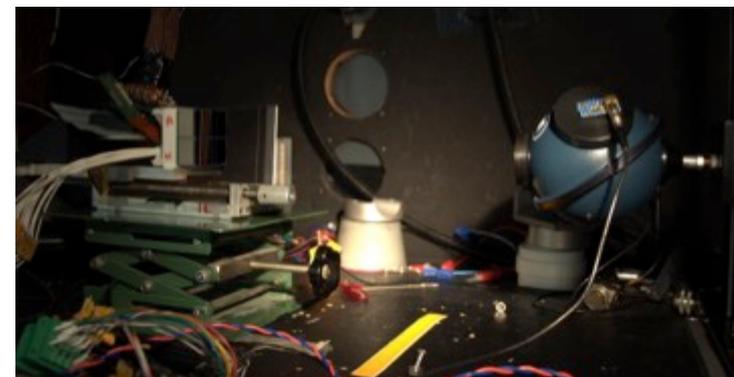
Test Interface :

EC units + EC-ASICs (performances)

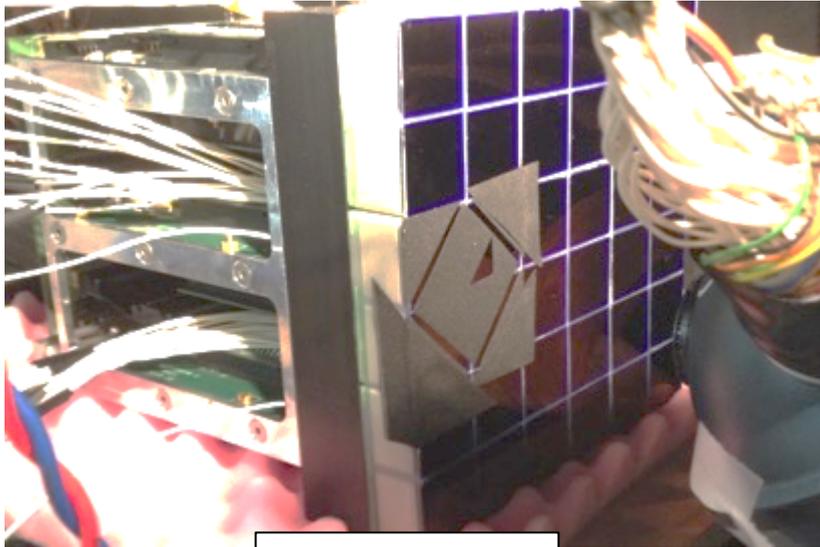
EC-ASICs + PDM board (consommation, controles/commandes)

PDM board + HVPS (controles/commandes)

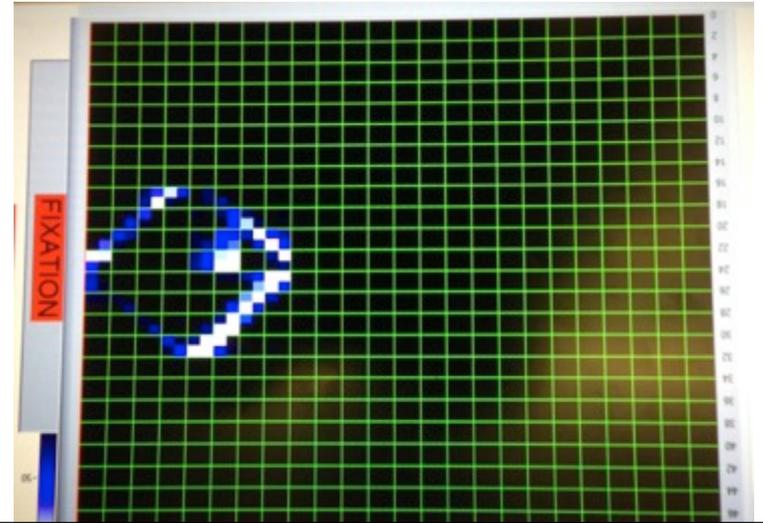
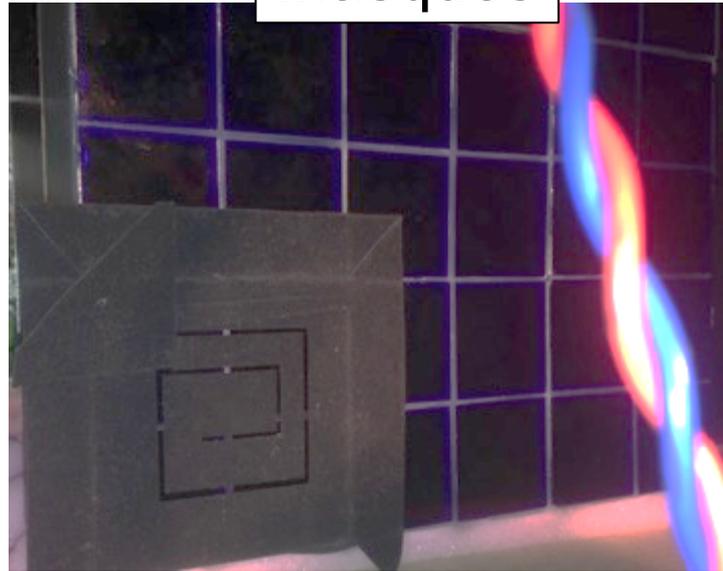
Calibration détecteur, mapping, etc.



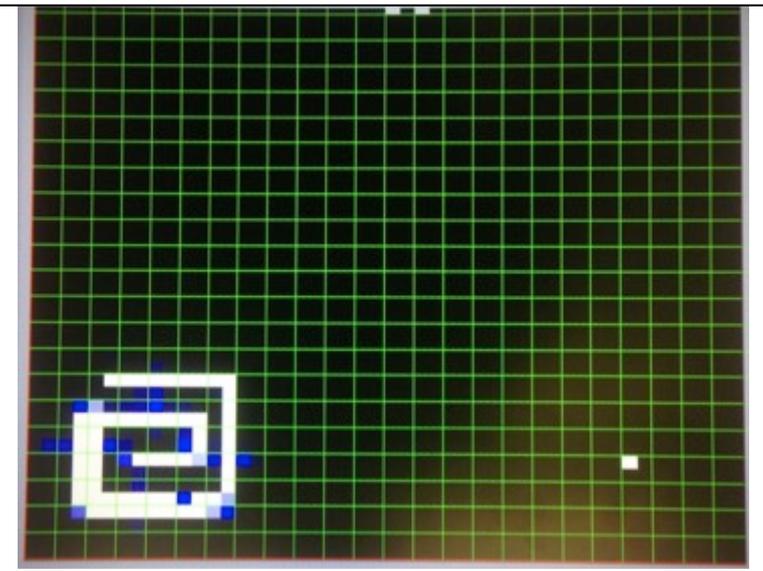
Exemple de test : le mapping



Masques



Reconstruction (p-c data)



Tests fonctionnels DP (extrait PAIE)



The instrument, on ground, can be completely controlled by the GSE (Ground Support Equipment).

2 Interfaces:

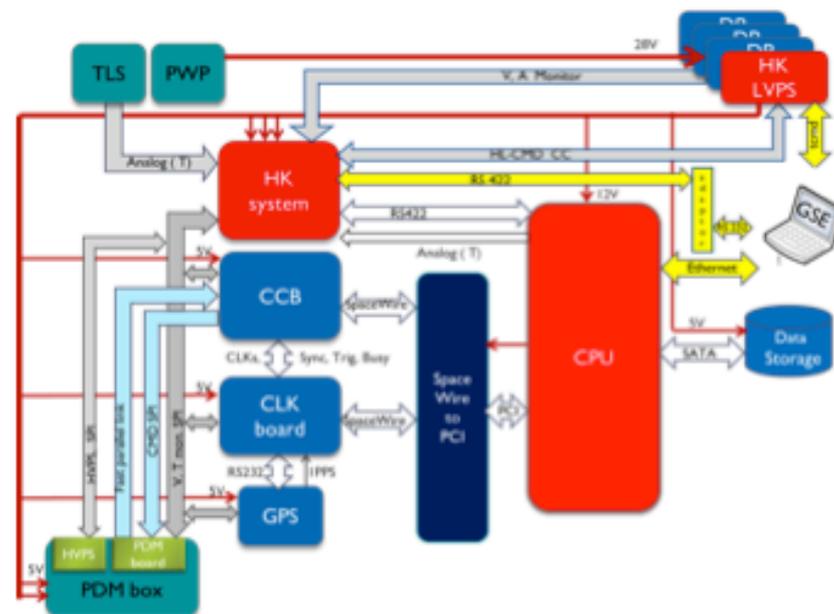
- GSE-HK Telemetry-Telecommand
- GSE-CPU Data-TM/TC

They simulate the control of the instrument as it should be performed by Siren system (CNES in flight communication). HK (RS 232 port) and CPU (TCP-IP)

Switching ON sequence

The sequence of operation successfully performed by sending command from the GSE console was:

- Switch ON the HK system (open drain switches simulated by a 2 jumpers DB9 connectors)
- Receiving of telemetry data (it starts automatically when HK is ON)
- Switch ON LVPS2 (CPU's disks) and CPU
- Read the status of the Contact Closure to verify that the operation has been properly execute
- Verify on the telemetry data the voltages and the absorbed currents for LVPS2
- Switch ON LVPS1 (GPS) (then verify the CC status and Voltages and currents on LVPS1)
- Switch ON LVPS1 (CLKB) (then verify the CC status and Voltages and currents on LVPS1)
- Switch ON LVPS1 (CCB) (then verify the CC status and Voltages and currents on LVPS1)
- Switch ON LVPS-PDM (PDM board) (then verify the CC status and Voltages and currents on LVPS-PDM)

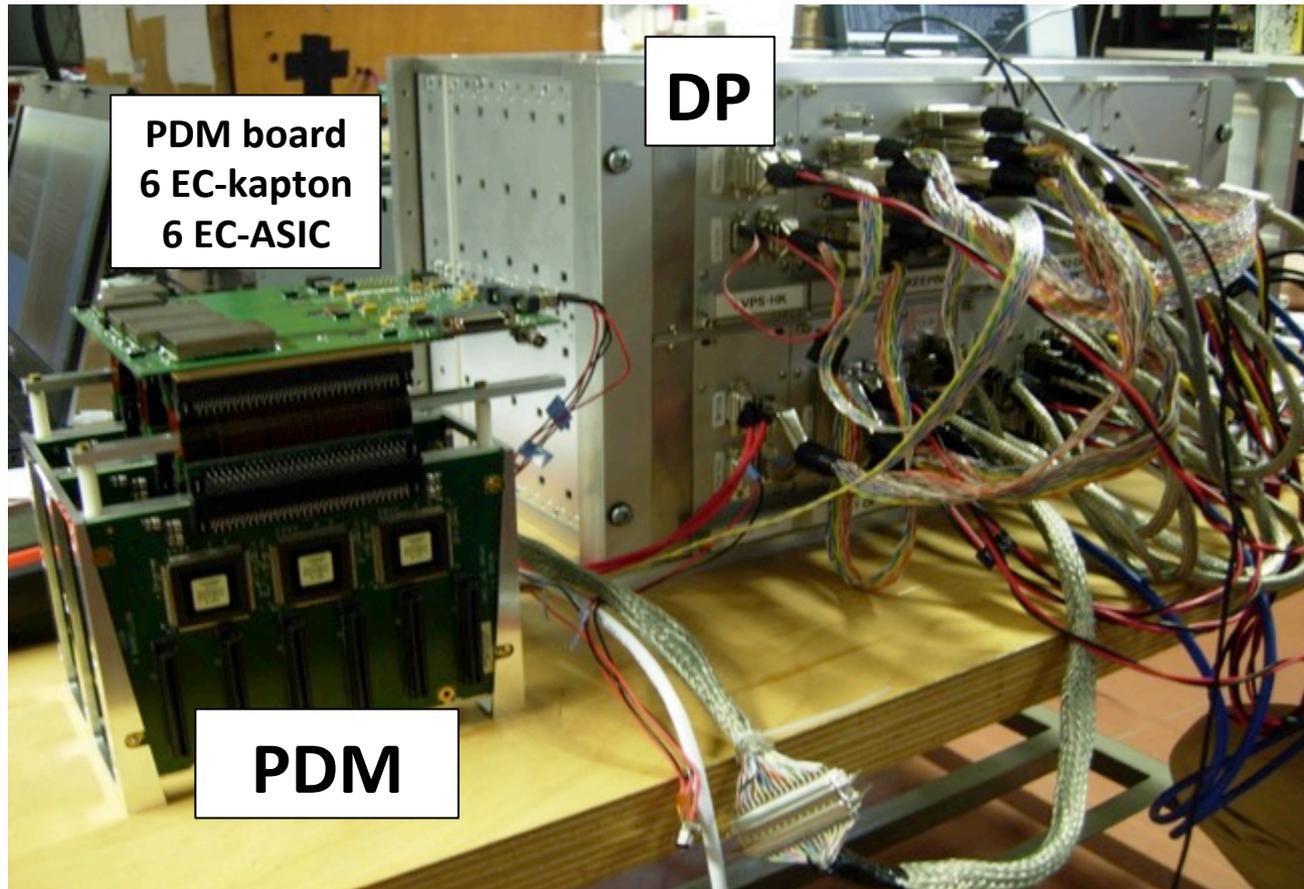


Tests thermiques Data processor



Sub-assembly	production			test			
	FM module	FM spare	FM cables	Functionality Conf. to spec.	Vacuum (3 mbar)	Thermal (-20 + 50)°C	Termo-vacuum
CPU	■	■	■	■	■	■	■
CCB	■	■	■	■	■	■	■
CLKb	■	■	■	■	■	■	■
GPS	■	■	■	■	■	■	■
HK	■	■	■	■	■	■	■
LVPS-HK	■	■	■	■	■	■	■
LVPS-DP1	■	■	■	■	■	■	■
LVPS-DP2	■	■	■	■	■	■	■
LVPS-PDM	■	■	■	■	■	■	■

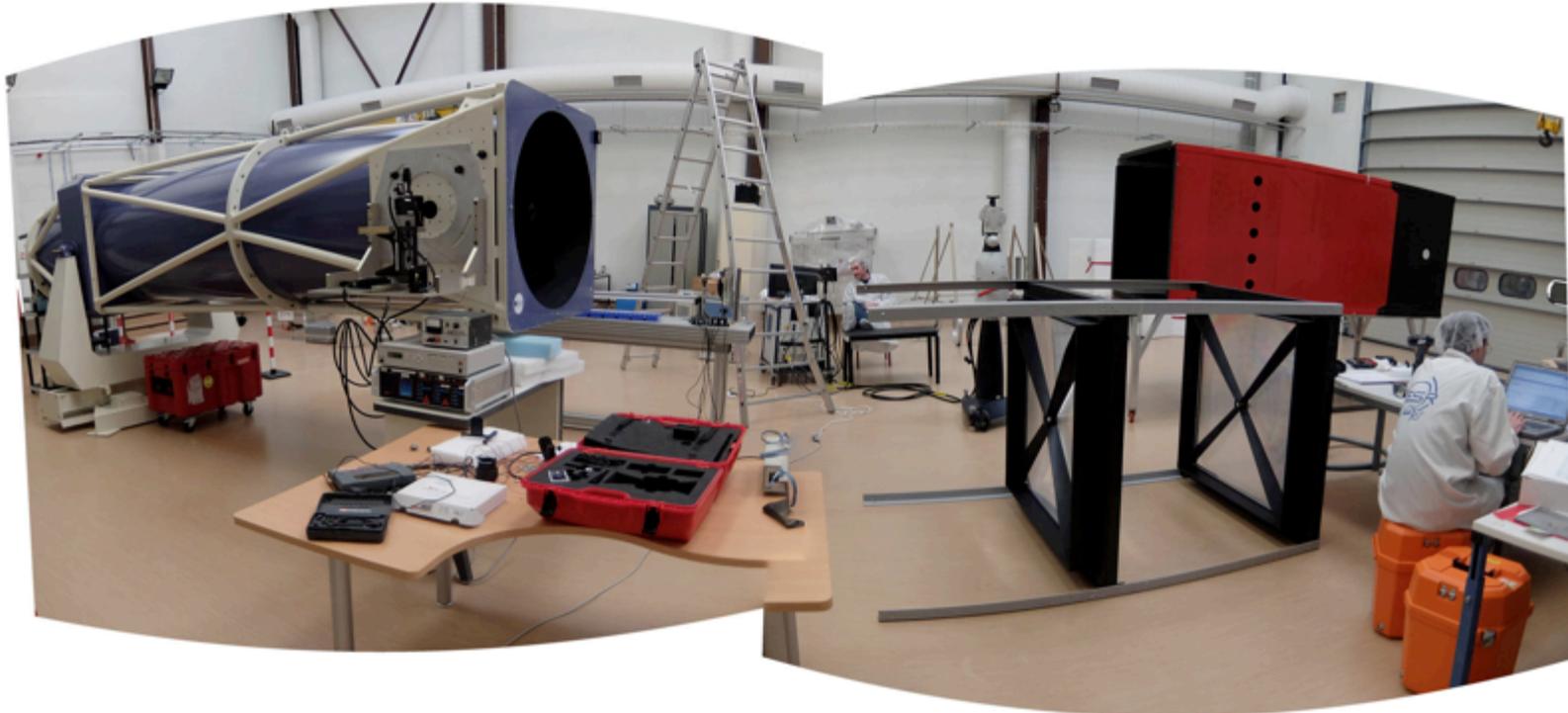
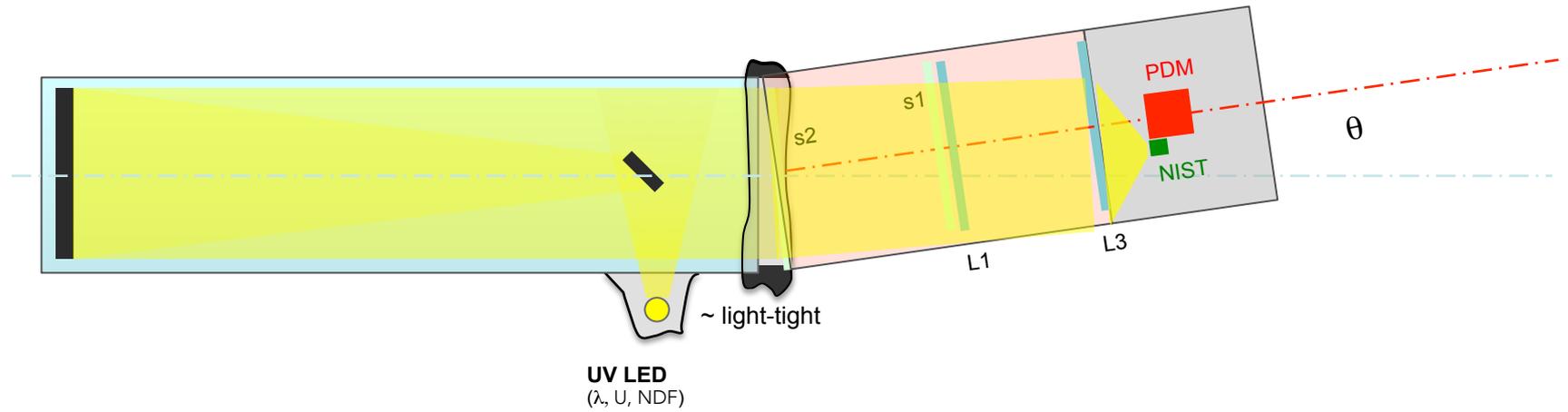
De début février à début mars 2014 : démarrage de l'intégration de la chaine électrique (câbles d'intégration non FM)



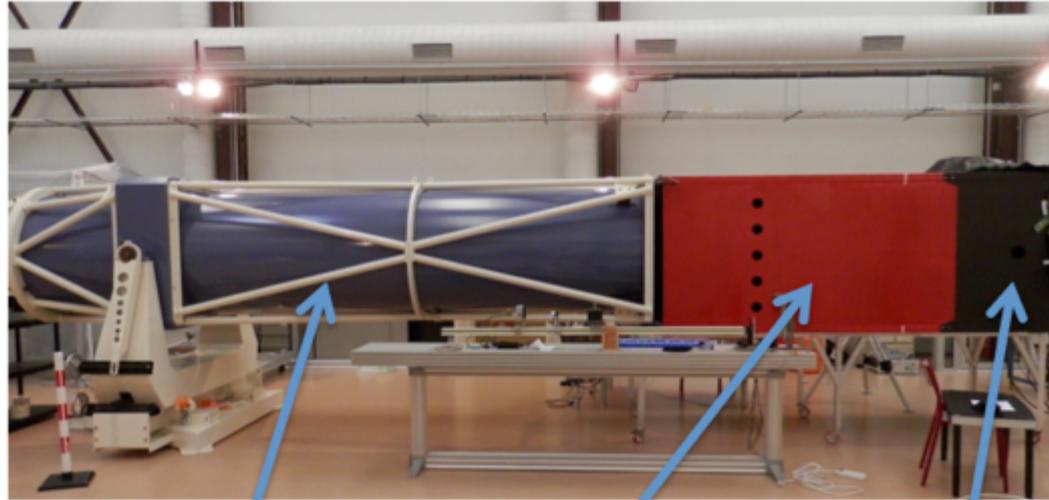
Tests thermiques (du 5 au 7 mars 2014, réservée des mois à l'avance)



Tests PDM+DP + optiques (@IRAP, Toulouse) mai 2014



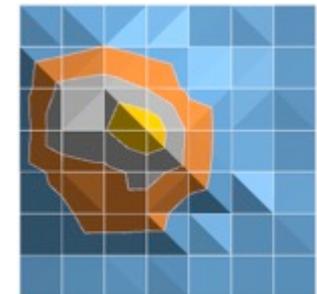
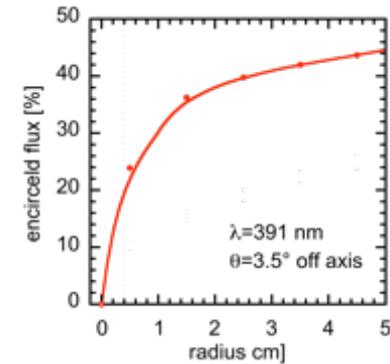
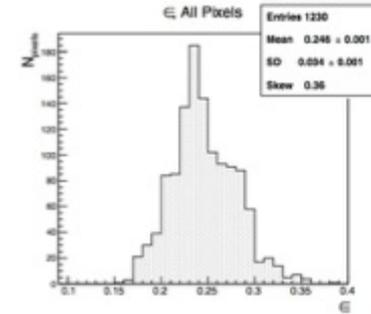
Tests PDM+DP + optiques (@IRAP, Toulouse) mai 2014



Collimator

Optical system

CCD+NIST
puis PDM



1 - Global Electronic Noise $\Delta \mathcal{E}_{FSnoise}$



2 - Global optical efficiency \mathcal{E}_{opt}



3 - Focal Spot size







Bilan Technique (BT) avant intégration finale

1.1. The connection of the CPU-FPGA Board (CPU) with the FPGA Board (FPGA)

The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board.

The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board.

1.2. The connection of the Microblaze (CPU) with the FPGA Board (FPGA)

The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board.

The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board.

1.3. CPU-FPGA Board - CPU

The CPU-FPGA board is connected to the CPU board via the CPU-FPGA board. The CPU-FPGA board is connected to the CPU board via the CPU-FPGA board. The CPU-FPGA board is connected to the CPU board via the CPU-FPGA board.

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1.4. CPU - FPGA

The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board.

The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board. The CPU board is connected to the FPGA board via the CPU-FPGA board.

Compte-Rendu d'Essai (CRE) après intégration finale

1.1. CPU-FPGA Board - CPU

1.2. CPU - FPGA

1.3. CPU-FPGA Board - CPU

1.4. CPU - FPGA

1.5. CPU-FPGA Board - CPU

1.6. CPU - FPGA

1.7. CPU-FPGA Board - CPU

1.8. CPU - FPGA

Manuel utilisateur EUSO-Ballon (hardware et software)

Domaines de fonctionnement

Mise en route

Tests bonne santé

Procédure avant-vol

Statuts, alarmes

Stratégie de prise de données

+ manuel logiciel instrument

Logiciel d'analyse et de visualisation rapide des acquisitions

Développement d'un logiciel et de sa documentation

Utilisé pendant l'intégration et le vol

EUSO-Balloon and EUSO-TA Manual
 Subsection of the manual for the EUSO software

Getting the data acquisition
 This section describes the steps to be followed to get the data acquisition.

Getting the data acquisition (instructions after the flight)

1. Prepare the software.
2. Prepare the hardware.
3. Prepare the data acquisition.
4. Prepare the data analysis.
5. Prepare the data visualization.

Preparing the data acquisition

Before the flight, the user must prepare the software and hardware to get the data acquisition.

1. Open the software. Review the user manual. Check the status of the software (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).
2. Check the status of the software. Review the user manual. Check the status of the software (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).
3. Check the status of the hardware. Review the user manual. Check the status of the hardware (EUSO-TA and EUSO-Balloon) and the software (EUSO-TA and EUSO-Balloon).
4. Check the status of the data acquisition. Review the user manual. Check the status of the data acquisition (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).
5. Check the status of the data analysis. Review the user manual. Check the status of the data analysis (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).
6. Check the status of the data visualization. Review the user manual. Check the status of the data visualization (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).

14. To get the data acquisition, the user must prepare the software and hardware to get the data acquisition.

15. To get the data analysis, the user must prepare the software and hardware to get the data analysis.

16. To get the data visualization, the user must prepare the software and hardware to get the data visualization.

17. Then open a new terminal (EUSO-TA) in the terminal window and enter the command `python3` to start the software. Review the user manual. Check the status of the software (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).

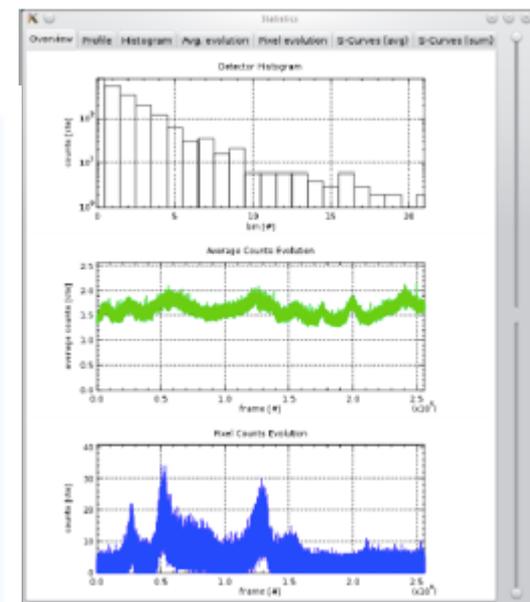
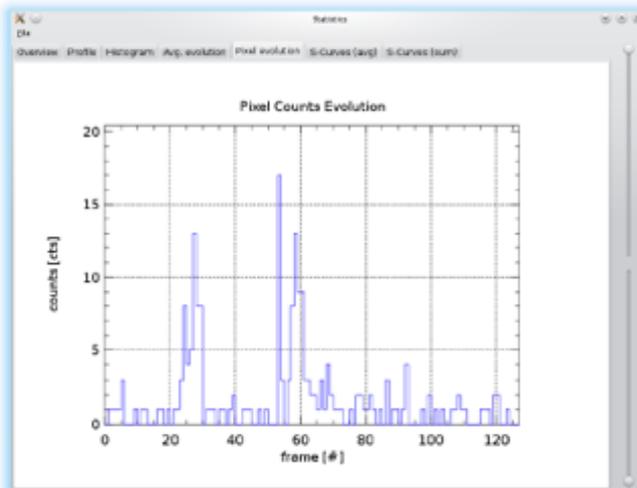
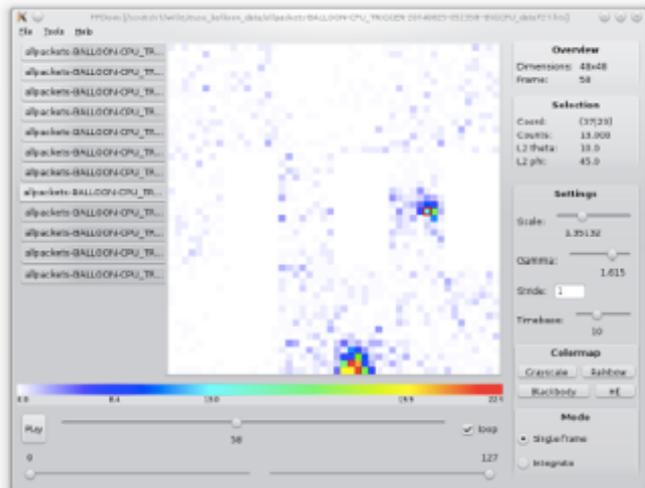
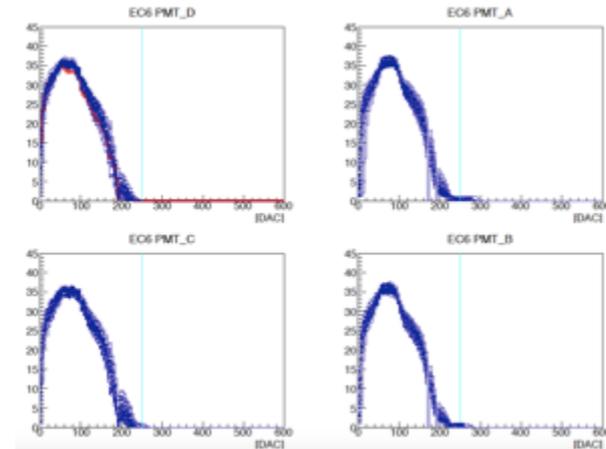
Starting the data acquisition

1. Open the terminal window.
2. Enter the command `python3` to start the software.
3. Check the status of the software. Review the user manual. Check the status of the software (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).
4. Check the status of the hardware. Review the user manual. Check the status of the hardware (EUSO-TA and EUSO-Balloon) and the software (EUSO-TA and EUSO-Balloon).
5. Check the status of the data acquisition. Review the user manual. Check the status of the data acquisition (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).
6. Check the status of the data analysis. Review the user manual. Check the status of the data analysis (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).
7. Check the status of the data visualization. Review the user manual. Check the status of the data visualization (EUSO-TA and EUSO-Balloon) and the hardware (EUSO-TA and EUSO-Balloon).

18. To get the data acquisition, the user must prepare the software and hardware to get the data acquisition.

19. To get the data analysis, the user must prepare the software and hardware to get the data analysis.

20. To get the data visualization, the user must prepare the software and hardware to get the data visualization.



Les points clés EUSO-Ballon :



14 Sept. 2011 : Phase A kick-off



18 Dec. 2012 : Critical Design Review



4 June 2014 : Flight Acceptance Review

Les anomalies...



ASIC Spaciroc 1 (Juillet 2012) :

- L'intégrateur de l'ASIC n'a pas une dynamique suffisante pour piloter les swiches et protéger les MAPMT

Solutions :

- Ne pas utiliser les SW, HK coupe les HV qd surcharge (plan B anticipé dans le doc. Risques)

Tests thermiques (mars 2014) :

- Impossible d'alimenter les 9 EC à 3mbar pour HV max (dû à une erreur de design PCB non détectée pdt le test du prototype seul)

Solutions :

- HV optimale (1100V) -> nominale (950V)

Réalisation des optiques (novembre 2013) :

- Anomalie réalisation L2 (erreur usine Japonaise)

Solutions :

- Config. à 2 Lentilles (plan B anticipé dans le doc. risques)

Anomalie fournisseur 'spider' (janvier 2014) :

- Les croisillons des lentilles déforment les lentilles, non-conformes aux specs (erreur fournisseur)

Solutions :

- Reprise des spiders et intégration des lentilles par l'IRAP (plan B anticipé dans le doc. risques)



Tests AIT (octobre 2013) :

- Carte Coréenne FPGA contraire aux specs (connecteurs signal et power identiques, même genre et sans détrompeur)
=> erreur de branchement

Conséquences : o Changement du FPGA et changement du genre du connecteur

Tests hors PAIE (document de tests) non spécifié (avril 2014) :

- Un test non spécifié des HV => Mesure destructive
(pas de spare à ce moment-là)

Conséquences : o 1 mois de délai (en travaillant les WE). Durant la réalisation du second FM, travail pour rendre les I/F plus fiables, modif du design mécanique, AIT + simple

Les problèmes...



Workpackage/organisation :

- L'équipe HVPS sous-dimensionnée

Solutions :

- Aide de l'APC (accord après réunions projets)

Workpackage/organisation :

- La Corée ne travaille pas sur son workpackage (la carte FPGA étant la pierre angulaire de la chaîne électronique)

Solutions :

- Reprise du WP par APC, embauche de la PhD Coréenne (retards & difficultés => pas de trigger on-line pour 1^{er} vol)

Suivi du CNES : problème potentiel de souplesse, en période critique

- Revue performances pendant l'intégration détecteur
- Exigence de fiches anomalie sous 48h et de documentation AIT pendant l'intégration

Solutions :

- Task force pour absorber le choc, transparent pour les équipes AIT

La campagne de vol : Welcome to Timmins !



Le site : l'aéroport civil de Timmins



Road to the tarmac



Prefa: WC, cafeteria, salle de réunions



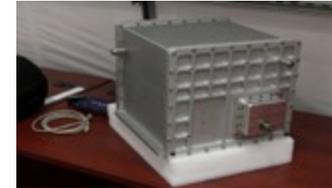
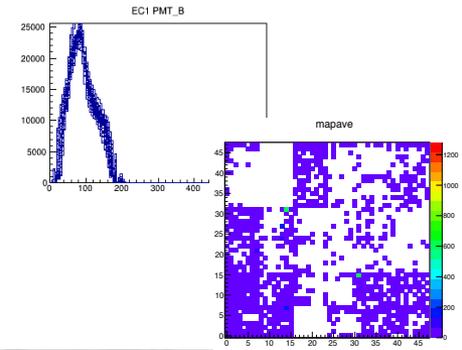
Bureaux et hall CNES

Containers & parking



Hall d'intégration

Campagne de vol : l'intégration avant-vol



Partage des tâches sur dans le hall d'intégration



Time	Chrono action	Coordinator	DP acquisition and monitoring	Secretary	Flasher/ Laser	Data analysis	Additional people (role)
8:30 - 10:00 am	Good health tests with laboratory power	Guillaume/Peter	Giuseppe, Claudio and Valentina	Camille M.	-	Simon/Hiroko	-
10:00 - 10:30 am	Good health test on battery	Guillaume/Peter	Giuseppe, Claudio and Valentina	Camille M.	Lawrence & Jim	Simon/Hiroko	Hector & Jörg (IR CAM status)
10:30 am - X pm	Recharge the SIREN and PASTIS batteries	Guillaume/Peter	-	Camille M.	-	-	-
12:00 am - 2:30 pm	Lunch buffet	Julio	-	-	-	-	Entire EUSO team
3:00 - 3:15 pm	ICDV initialisation	Guillaume/Peter	-	Sylvie D.	-	-	Xavier (CNES)
3:15 - 3:30 pm	SIREN - NSO initialisation	Guillaume/Peter	Giuseppe, Claudio and Valentina	Sylvie D.	-	-	-
3:30 - 4:00 pm	End to end good health test	Guillaume/Peter	Giuseppe, Claudio and Valentina	Sylvie D.	-	Simon/Hiroko	-
4:00 - 4:15 pm	Check structure ready for roll - out	Guillaume/Peter	-	Julio	-	-	Gilles
4:15 - 4:30 pm	Instrument put at its loading location	Guillaume/Peter	-	Julio	-	-	EUSO team to help
4:30 - 4:45 pm	Check GPS signal (US)	Guillaume/Peter	-	Julio	Lawrence & Jim	-	-
4:45 - 5:15 pm	Roll - out to tarmac	Guillaume/Peter	-	Julio	-	-	Local team + Gilles
5:15 - 5:45 pm	Preparation on tarmac	Guillaume	-	Camille C.	Lawrence & Jim	-	Local team + Gilles + Peter
5:45 - 6:00 pm	Good health tests with generator	Guillaume	Giuseppe, Claudio and Valentina	Camille C.	Lawrence & Jim	Simon/Hiroko	Local team + Gilles + Peter
6:00 - 6:15 pm	Good health tests on battery	Guillaume	Giuseppe, Claudio and Valentina	Camille C.	Lawrence & Jim	Simon/Hiroko	Local team + Gilles + Peter
6:15 - 7:00 pm	Finalisation of the instrument: ICDV calib, hatch joint, hatch fixation, IR CAM cover to remove, LEDs flasher, additional box finalised and fixed	Guillaume	Giuseppe, Claudio and Valentina	Camille C.	Lawrence & Jim	Simon/Hiroko	Local team + Gilles + Peter
7:00 - 7:15 pm	Short run (100 packets) at DAC 250	Guillaume	Giuseppe, Claudio and Valentina	Camille C.	Lawrence & Jim	Simon/Hiroko	Local team + Gilles + Peter
7:15 - 8:00 pm	Remove before flight (skier, covers), heating the lens	Guillaume	Giuseppe, Claudio and Valentina	Camille C.	Lawrence & Jim	Simon/Hiroko	Local team (Inflation of the balloon) + Gilles + Peter
8:00 - 8:15 pm	LAUNCH						Team near tarmac
8:00 - 10:30 pm	Ascending (s-curves every 10mn)	Guillaume/Peter	Giuseppe, Claudio and Valentina	Julio	Lawrence & Jim	Simon/Hiroko	CNES
10:30 - 11:00 pm	Assess location and darkness	Guillaume/Peter	Giuseppe, Claudio and Valentina	Julio/Jörg	Lawrence & Jim	Simon/Hiroko	CNES
11:00 - 1:00 am	Standard acquisition procedure	Guillaume/Peter	Giuseppe, Claudio and Valentina	Jörg	Lawrence & Jim	Simon/Hiroko	CNES
1:00 - 2:00 am	Standard acquisition procedure	Guillaume/Peter	Giuseppe, Claudio and Valentina	Sylvie D.	Lawrence & Jim	Simon/Hiroko	CNES
2:00 - 3:00 am	Standard acquisition procedure	Guillaume/Peter	Giuseppe, Claudio and Valentina	Camille M.	Lawrence & Jim	Simon/Hiroko	CNES
3:00 - 4:00 am	Alternative configuration run	Guillaume/Peter	Giuseppe, Claudio and Valentina	Aera	Lawrence & Jim	Simon/Hiroko	CNES

Chronologie négative pour le jour du vol



Tests to be done before launch (around 8:30 am)

They have to be performed 1h30 - 2h before the flying decision.

The instrument has

- Instrument i
- Visual details
- Light tight in
- PASTIS and S
- SIREN power
- SIREN in wir
- GSE through
- IR CAM filled

7:00 pm (TBC) OK => unpacking of the balloon

- Electronics still ON -> short (100 packets) run at DAC 250
- Electronics status (HK/CPU)

cable plugged on the

Only thing different:

7:15 pm (TBC): OK => Start filling of the balloon: 45' before launch

Test sequence:

- DP switch-on
- switch-on PD
- good-health t
 - o Stand
 - o HVPS
 - o LED O
 - o ramp
 - o increa
 - o Stand
 - o HV OF

- Remove "before flight" items

- o Unfix skier
- o Pull the tarp on the vents

ain)

main gate) using

- Skier on the ground below the instrument
- Heater (110 V) on the skier (to heat the first lens)
- Switch on GO-PRO with a stick (2 sec push) - check LED (red flash every ~2 sec)

the skate boards.

- o LED ON (3.2 V) - check NIST (~40 pW)
- o HV ON (950 V)
- o Standard s-curves -> analysis

- Switch OFF DP and PDM (2')
- End-to-end test on FM batteries (20'):
 - o Remove power supply cable from the hatch and start to be used)
 - o DP switch ON sequence
 - o Switch ON PDM
 - o HVPS ON (50V), LED OFF, check HVPS status
 - o 100 events run at fixed threshold (DAC 250) -> analysis
 - o Switch OFF PDM and DP
 - o Remove Power Plug from hatch
- IR CAM (20'):
 - o Switch ON -> status
 - o Fix the connectors cover (16 screws with 3/32 allen key)
 - o Fix styrofoam protection (4 screws with 5/32 allen key)
 - o Stays ON -> status
- Flashers: OK (phone call to the helicopter base)

=> Decision GO/NO-GO EUSO project

Meteo briefing at 11:30 am

Around 3:00 pm:

- Put ICDV plug on the hatch (CNES team: Xavier): 15'

WELLSVILLE SOLUTIONS:

- Auxiliary balloon test (lift the instrument)
- Configure everything for the tests (ladder, power supply, etc)
- Generator + 28V lab power supply

Connect external cable from power supply to the hatch

Test GO/NO-GO:

- o DP switch ON sequence (checking power consumption)
- o Switch ON PDM
- o HVPS ON (50V), LED OFF, check HVPS and NIST status
- o Standard s-curves -> analysis
- o Switch OFF PDM and DP

At 6:30 pm:

- Unplugged the power cable from the hatch
- Power plug on the hatch to replace the power cable and use the batteries
- Test GO/NO-GO:
 - o DP switch ON sequence (checking power consumption)
 - o Switch ON PDM
 - o HVPS ON (50V), LED OFF, check HVPS and NIST status
 - o Standard s-curves -> analysis
- IR CAM status - remove red cover (REMOVE BEFORE FLIGHT LABEL) : need 3/32 allen key
- Flasher status (LEDs on the roof)
- ICDV initial calibration (gondola aligned to the landing track of the airport, use of google map)
- Prepare the silicon joint of the cap of the hatch
- Close hatch (tight screwing)
- Close the additional box (with gelger, Iphone and NIST monitor) after FM batteries installed
- Remove securities and ladders

OK for launch ?

- Around 10:30 am: Recharge SIREN/PASTIS batteries (< 6h)
- NO INTERVENTION on the instrument allowed after that point



Fichier log + télémétrie

Durant le vol, on note toutes les actions (acquisitions, changements de configurations, reboot, reset, etc)

La télémétrie enregistre elle aussi son propre fichier log (Températures, statuts des sous-systèmes, noms des fichiers de données, etc)

Log Projet

```

18:43 (UTC) short run CPU trigger, 5 packets, HV OFF, DAC = adjusted, Gain table =
equalized => filename "20140824-184133"

18:53 (UTC) Checking low light level (NIST = 1 pW)
18:53 (UTC) Ramping up HV up to 900V
18:59 (UTC) HV On at 950V

18:59 (UTC) temperatures (Disc1, CPU, Disc2, SP2 // FPGA plate, FPGA braid, DP side, PDM
cavity, ICDV cavity):
37, 59, 37, 51 // 41, 27, 29, 26, 25

19:02 (UTC) 3 runs CPU trigger HV ON, LED OFF:
run 1: Gain = equalized, DAC = 250 => filename "20140824-190218"
run 2: Gain = equalized, DAC = adjusted => filename "20140824-190245"
run 3: Gain = 64, DAC = adjusted => filename "20140824-190343"

19:06 (UTC) starting s-curve with Gain = equalized, DAC = 0 to 300, step 5, 5 packets (HV ON,
LED OFF) => filename "20140824-19???"

19:09 (UTC) temperatures (Disc1, CPU, Disc2, SP2 // FPGA plate, FPGA braid, DP side, PDM
cavity, ICDV cavity):
37, 59, 37, 51 // 41, 27, 30, 26, 25

19:11 (UTC) Turning LED ON (3.0 V, NIST = 21 pW)

19:11 (UTC) CPU trigger, 200 packets, GAIN = 64, DAC = adjusted => filename "20140824-
191158"

19:12 (UTC) CPU trigger, 200 packets, GAIN = equalized, DAC = adjusted => filename
"20140824-191236"

19:13 (UTC) CPU trigger, 200 packets, GAIN = 64, DAC = 250 => filename "20140824-
191317"

19:14 (UTC) taking s-curve, from 0 to 500, step 5, 20 packets, GAIN = equalized => filename
"20140824-191429"

19:03 (UTC) temperatures (Disc1, CPU, Disc2, SP2 // FPGA plate, FPGA braid, DP side, PDM
cavity, ICDV cavity):
38, 60, 38, 51 // 41, 27, 30, 26, 25

```

```

19:34 (UTC) switching LED OFF (from [3.0 V, NIST = 21 pW] to 3 pW)
19:35 (UTC) switching HV OFF (?)

```

Log HK

```

GSE SC 2014-Aug-25 00:30:44 -->DONE Signal detected from CLKB
GSE SC 2014-Aug-25 00:30:44 -->No ALARM from CLKB
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->DONE Signal detected from CCB
GSE SC 2014-Aug-25 00:30:44 -->No ALARM from CCB
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->***HouseKeeping*** Firmware 6.0.6
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->TempHK 35.81, 85.70, Temperatures: PCB01-HK, Reg5V-HK
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->CPUThermistor 37.06, 58.59, 37.29, 50.34 Temperatures: DISC1, CPU, DISC2, SP2
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->LVPS-HK, 11.574, 146, 3.223, 190, V12V-HK, I12V-HK, V3.3V-HK, I3.3V-HK
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->TherLVPS2-DP 47.61, 52.90, 58.97, Temperatures: LVPS-DP2/ DC1, DC2, DC3
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->TherLenses 39.54, 27.61, 30.43, 25.03, 26.87, 61.22, Temperatures: PDM plate, PDM thermal braid,
DP, PDM cavity, ICDV cavity, last to be discarded
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->LVPS-DP1, 5.037, 1119, 4.961, 386, 4.947, 117, V5V-CCB, I5V-CCB, V5V-CLKB, I5V-CLKB, V5V-GPS, I5V-GPS
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->LVPS-DP2, 11.843, 982, 5.097, 239, V12V-CPU, I12V-CPU, V5V-DST, I5V-DST
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->LVPS-PDM, 2.848, 1647, 5.517, 0, V5.5V-PDMB, I5.5V-PDMB, V5.5V-EC, I5.5V-EC
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->CLKB, 44.779, 0.989, 2.471, From CLKB: Temperature, Vcint, Vcaux
GSE SC 2014-Aug-25 00:30:44 -->CLKB-date, 1, 1, 2004 Month, date, year
GSE SC 2014-Aug-25 00:30:44 -->CLKB-time, 12, 43, 15, c, ccfe Hours, Minutes, seconds, fractional second
GSE SC 2014-Aug-25 00:30:44 -->CLKB-position, 0, 0, 0, 0, 0, 0 Latitude, longitude, height
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->CCB, 5a, a5, 3.296, 0.046, 2.470, 0.830, 1.197, 0.194, 4.860, 1.799, 37.369, 40.369, From CCB: test values(5a,a5)
V3.3V, I3.3V, V2.5V, I2.5V,
V1.2V, I1.2V, V5V, I1.8V,
T-BOARD, T-FPGA
GSE SC 2014-Aug-25 00:30:44 -->HVPS, 0, 0, 0 Status for the 3 HVPS
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->PDM, -323.150, ffff, ab0f, ffff, ffb, 606 From PDM board: Temperature, VEC2, VEC2, VEC3, VFPGA1, VFPGA2
GSE SC 2014-Aug-25 00:30:44 -->
GSE SC 2014-Aug-25 00:30:44 -->GPS, 27.05, 3.14, GPS information: Temperature, Voltage

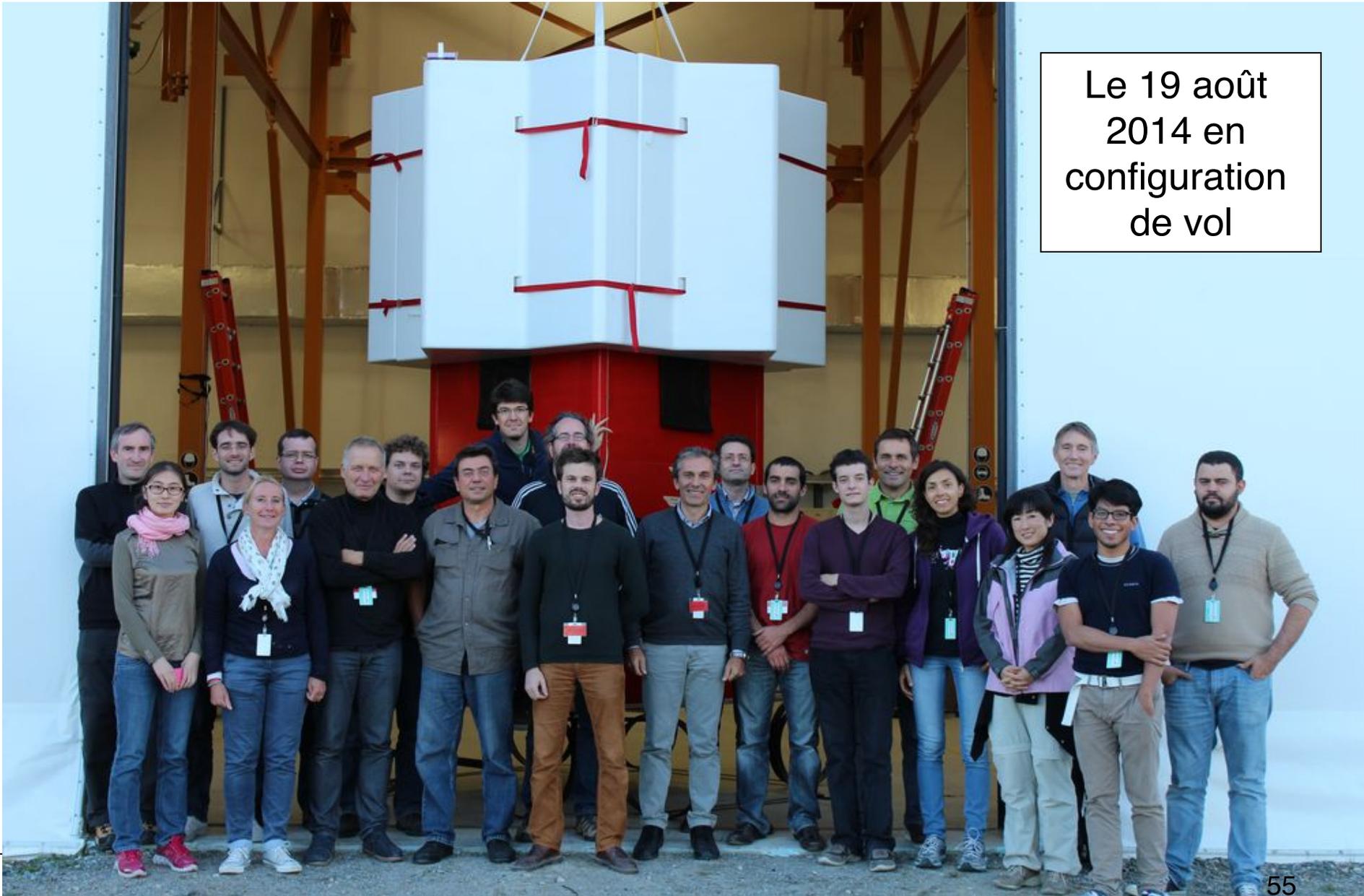
```

NB: CCB currents are in A
The others are in mA

Configuration de vol (après 9 jours)

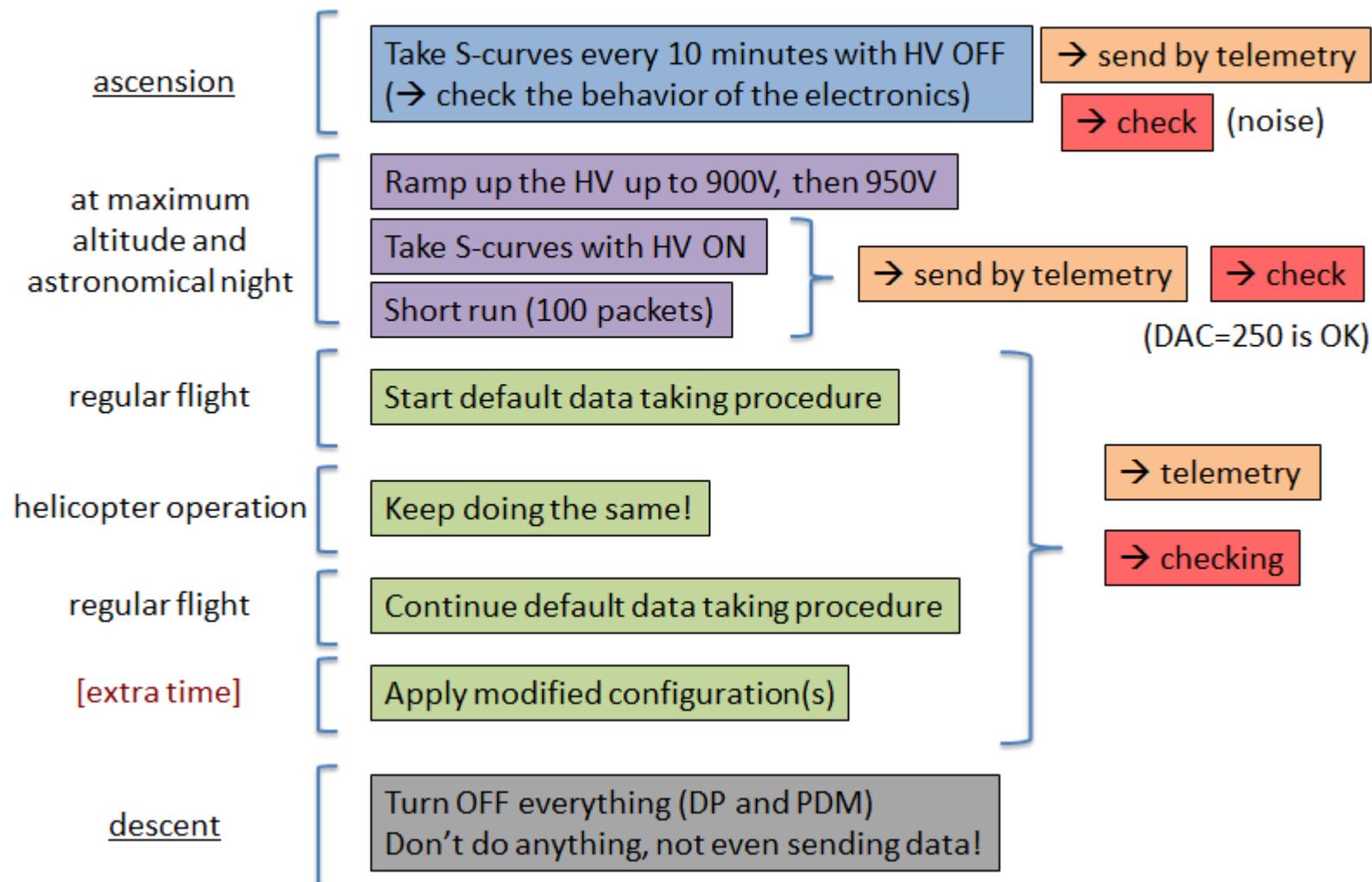


Le 19 août
2014 en
configuration
de vol



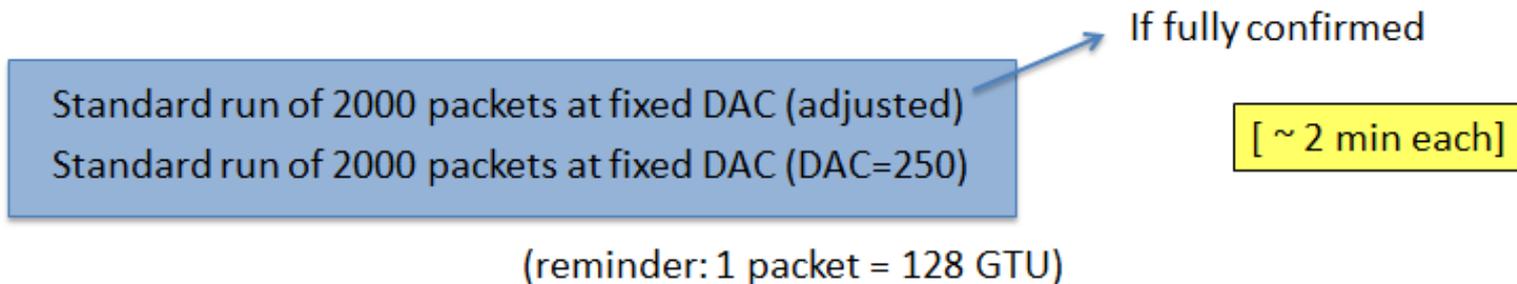


Sequence of operations

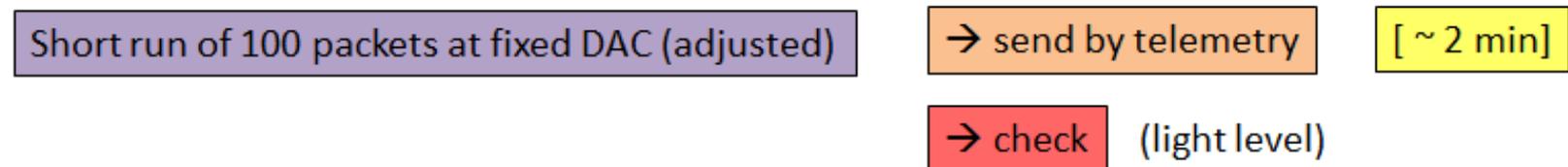




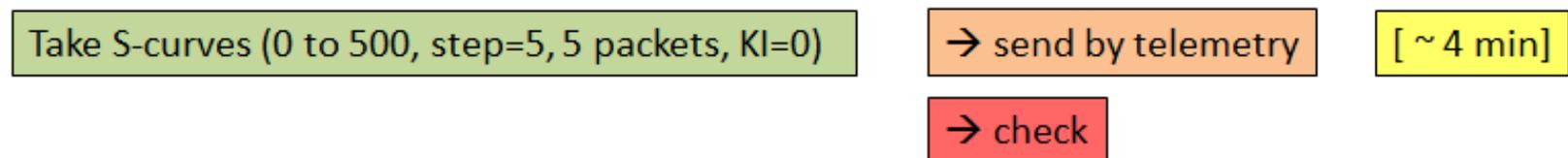
Default data taking procedure



Every 10 minutes:



Every 30 minutes:



(DAC position OK, degradation...)





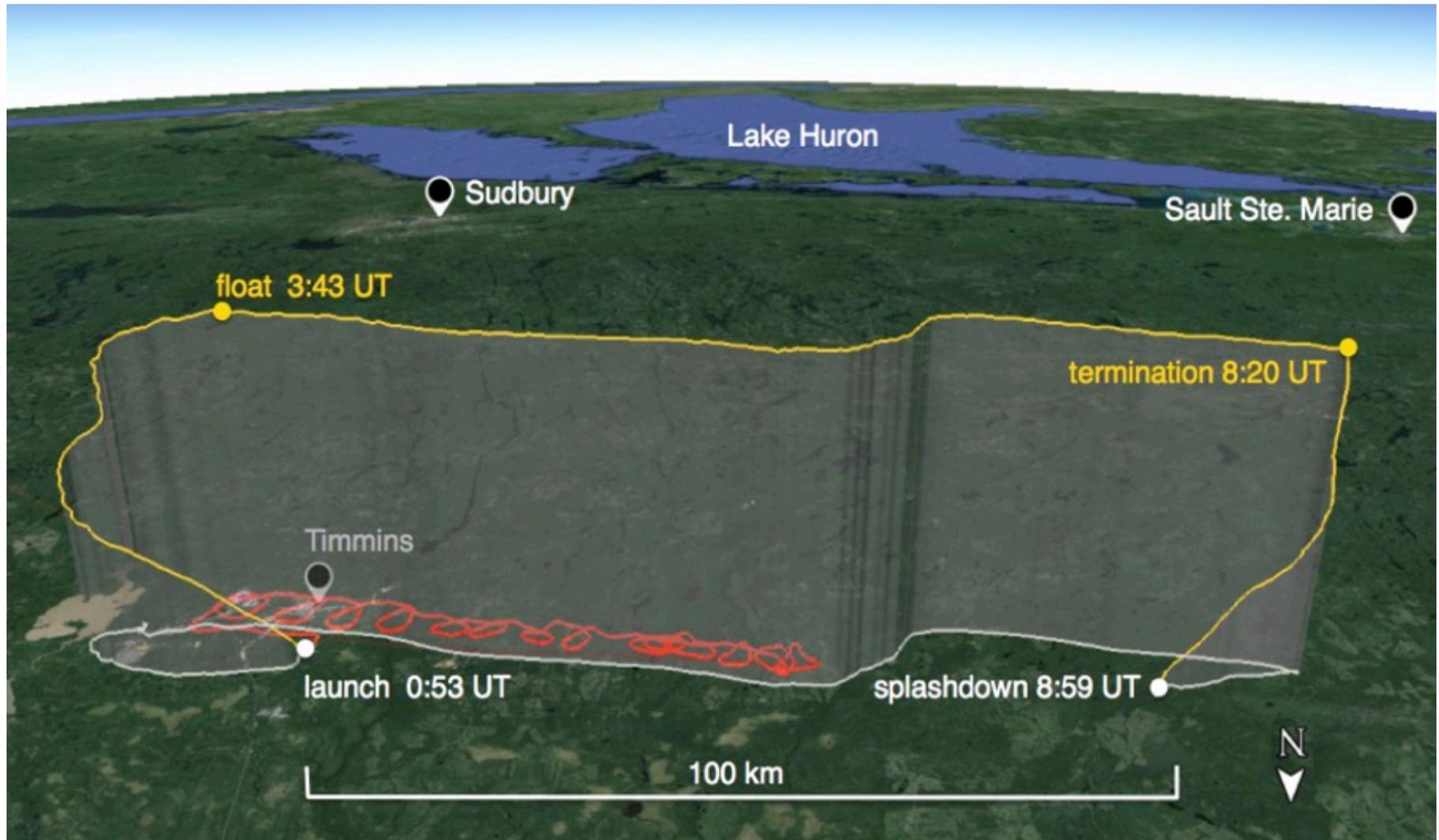
Le 24 août
2014 le jour
du vol



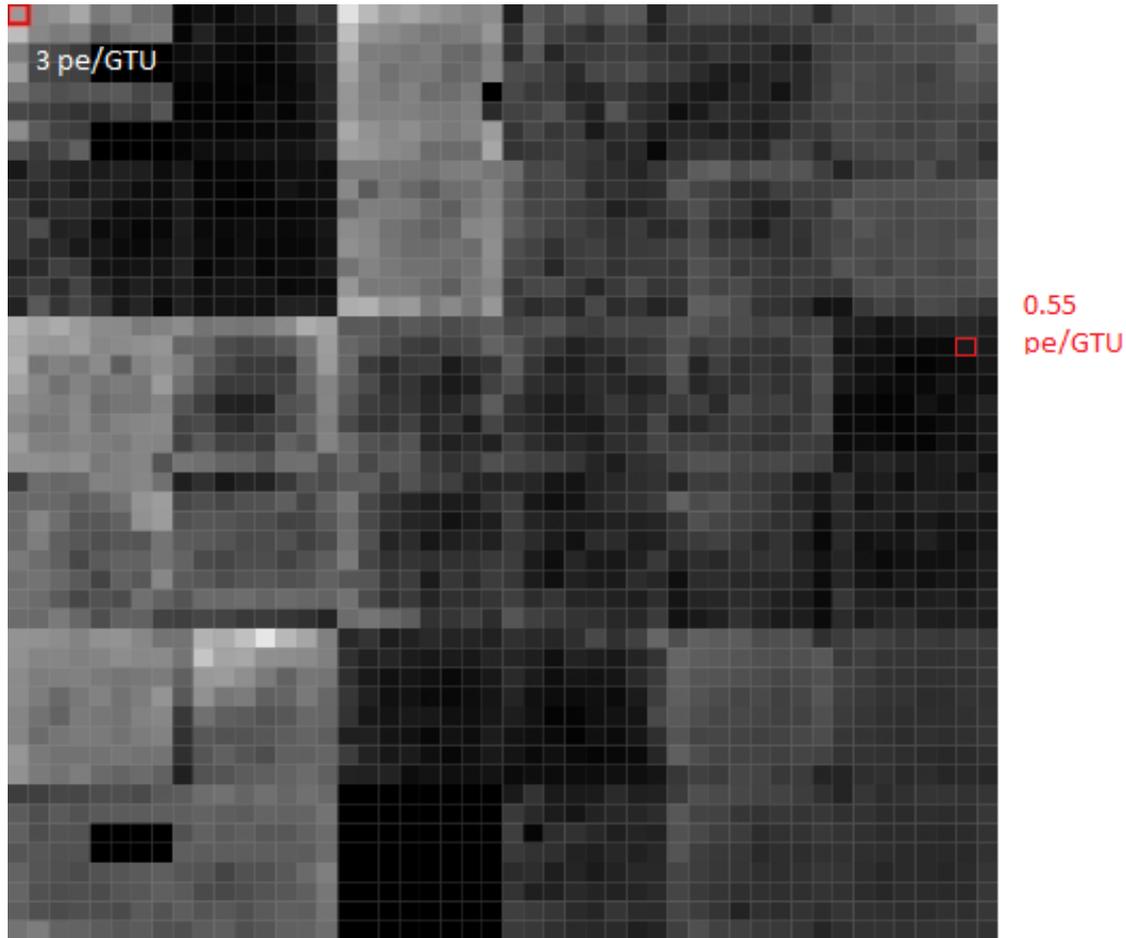
Quelques photos du vol (avant les vidéos)



Trajectoire du vol ballon (jaune) et hélico (rouge) 3D



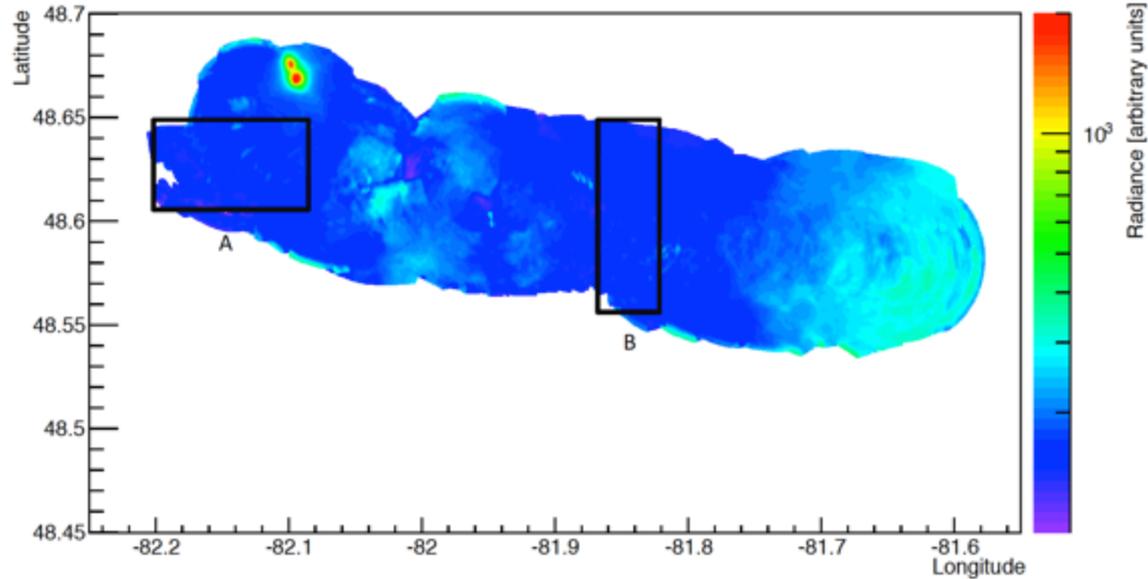
EUSO-Ballon : première lumière du détecteur !



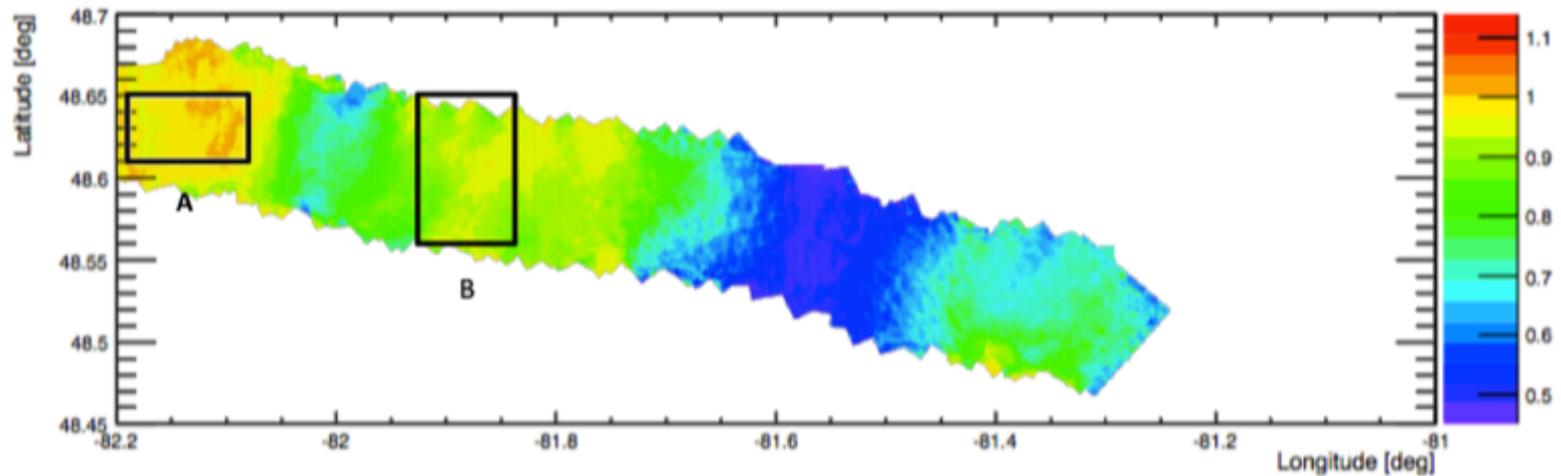
EUSO-Ballon : premières cartes UV et IR



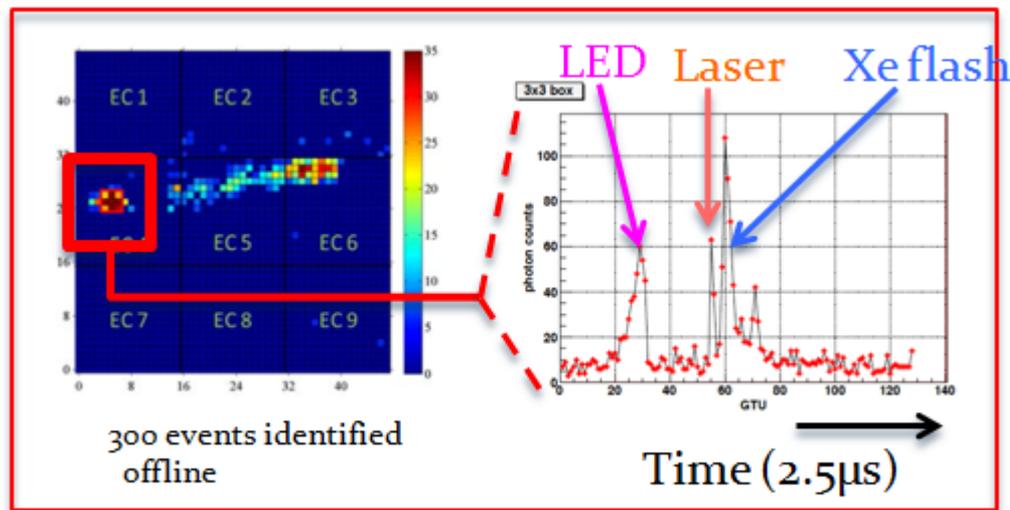
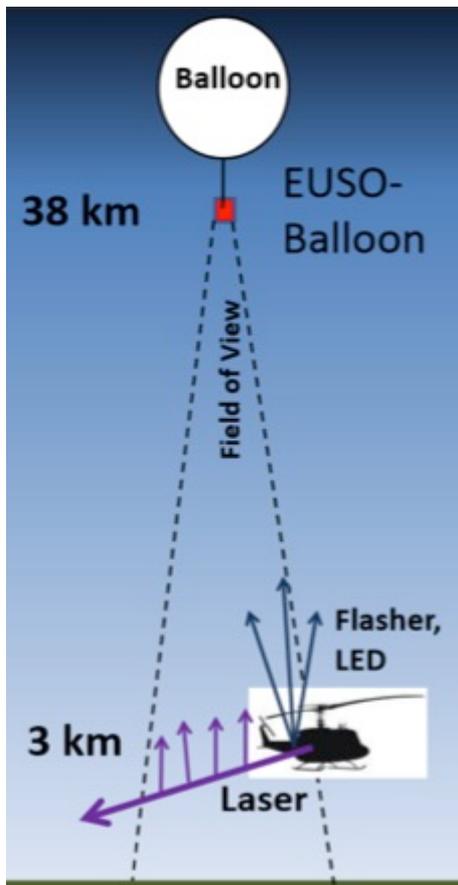
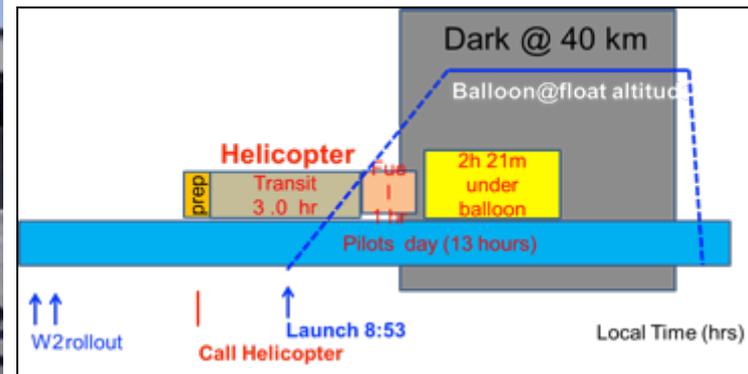
UV radiance map



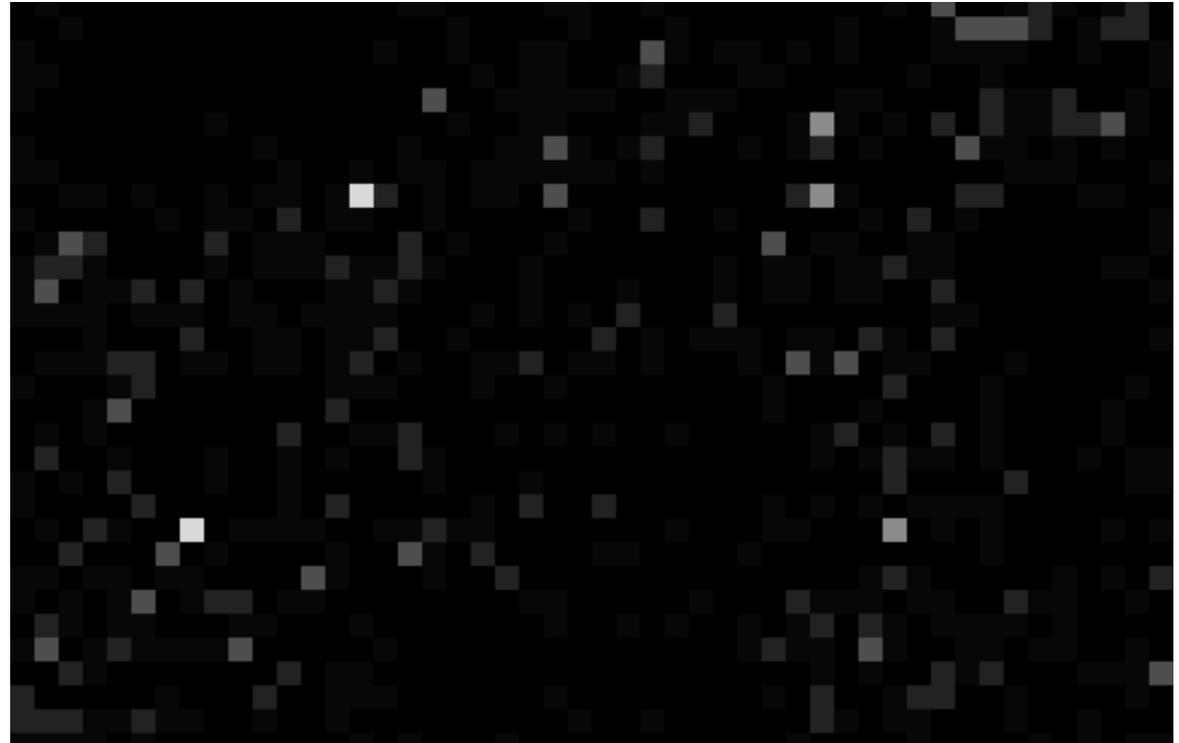
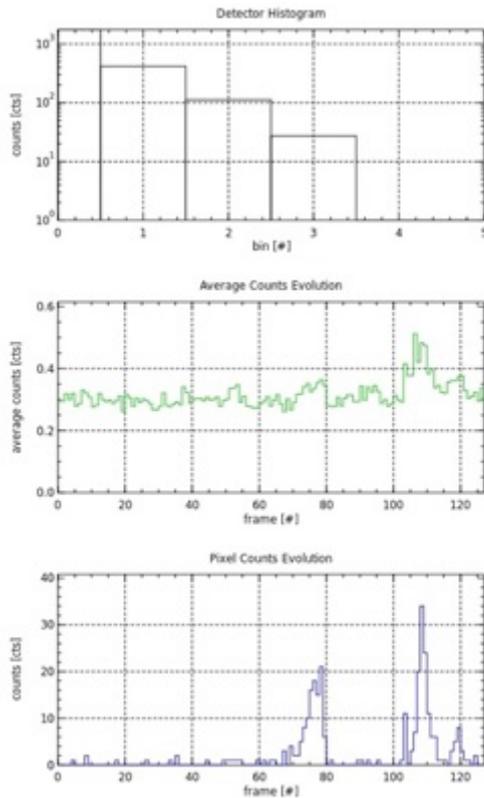
EUSO-Balloon: Map of IR radiance [relative units], 03:43:32 - 05:47:58 (UTC), FoV of PDM



Générations d'évènements simulés à bord d'un hélico



EUSO-Ballon : première détection d'événement simulé !



Spot laser (hélicoptère)



Calibration absolue PDM

Efficacité du système optique (throughput, PSF, champ: comparaison avec les simulations)

➔ Détection et reconstruction des événements lasers et flashers

Altitude des nuages: application des algorithmes aux données de vol (+ comparaison avec les données météo locales)

➔ Bruit de fond UV et variabilité

Événements atmosphériques, météores, avions... rayons cosmiques ! (→ limites?)

Étude comparative de différents (compte tenu du bruit de fond mesuré et des simulations de gerbes)

➔ Acceptance en fonction de E (déduite des mesures de bkgd UV)

➔ Prédiction de taux de comptage pour un vol long

Présentation globale : objectifs



Chaque niveau d'objectif a été partiellement atteint dès le premier vol :

Niveau A : Test à l'échelle 1 de la technologie JEM-EUSO

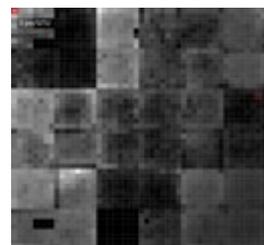
Alimentation haute-tension, commande des **switches** HT pour la réduction ultra-rapide du gain des PMTs, électronique de front-end (ASICs, FPGA...)

Hardware et **software pour les triggers** et la reconnaissance des gerbes



Niveau B : Etude du bruit de fond JEM-EUSO

Avec une résolution suffisante \rightarrow taille du pixel au sol $<$ celle de JEM-EUSO, acquisition de données type JEM-EUSO depuis une plateforme de type spatial, test et optimisation des algorithmes de trigger en conditions réelles et variables



Niveau C : Mission précurseur

Première détection d'une gerbe de **rayon cosmique** par le dessus ?

Détection d'événements induits par laser ou flashes ?

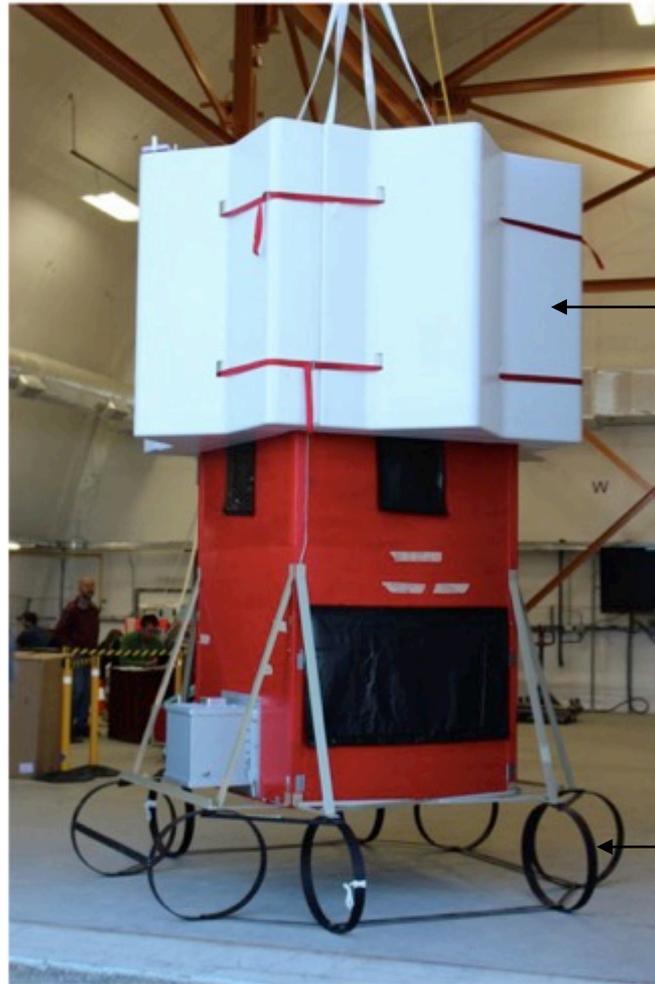


Le second vol devra valider les switches et surtout la détection par le trigger de rayons cosmiques (validé au sol en 2015 par l'équipe dans le cadre de TA-EUSO)



**Nacelle
étanche
(design)**

Pas de sous-
système
contre les
parois



Les flotteurs

Les crashpads

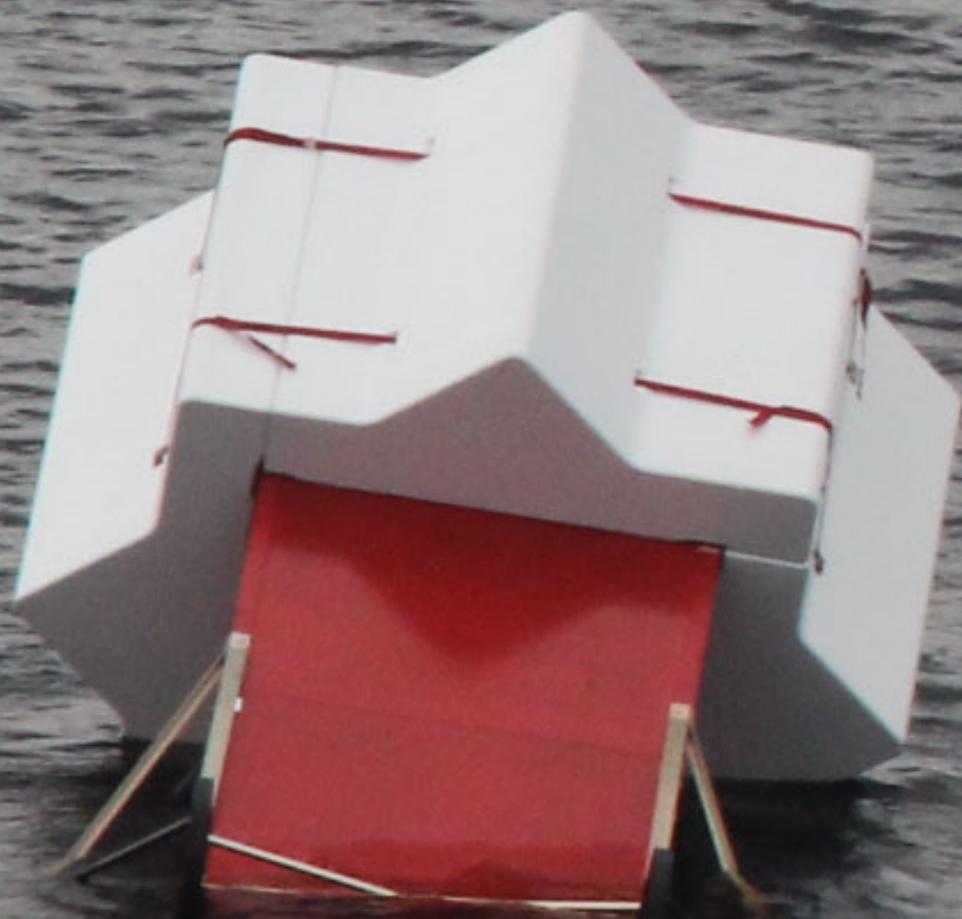
Atterrissage : zone la plus sèche possible (Canada: 3 millions de lacs)

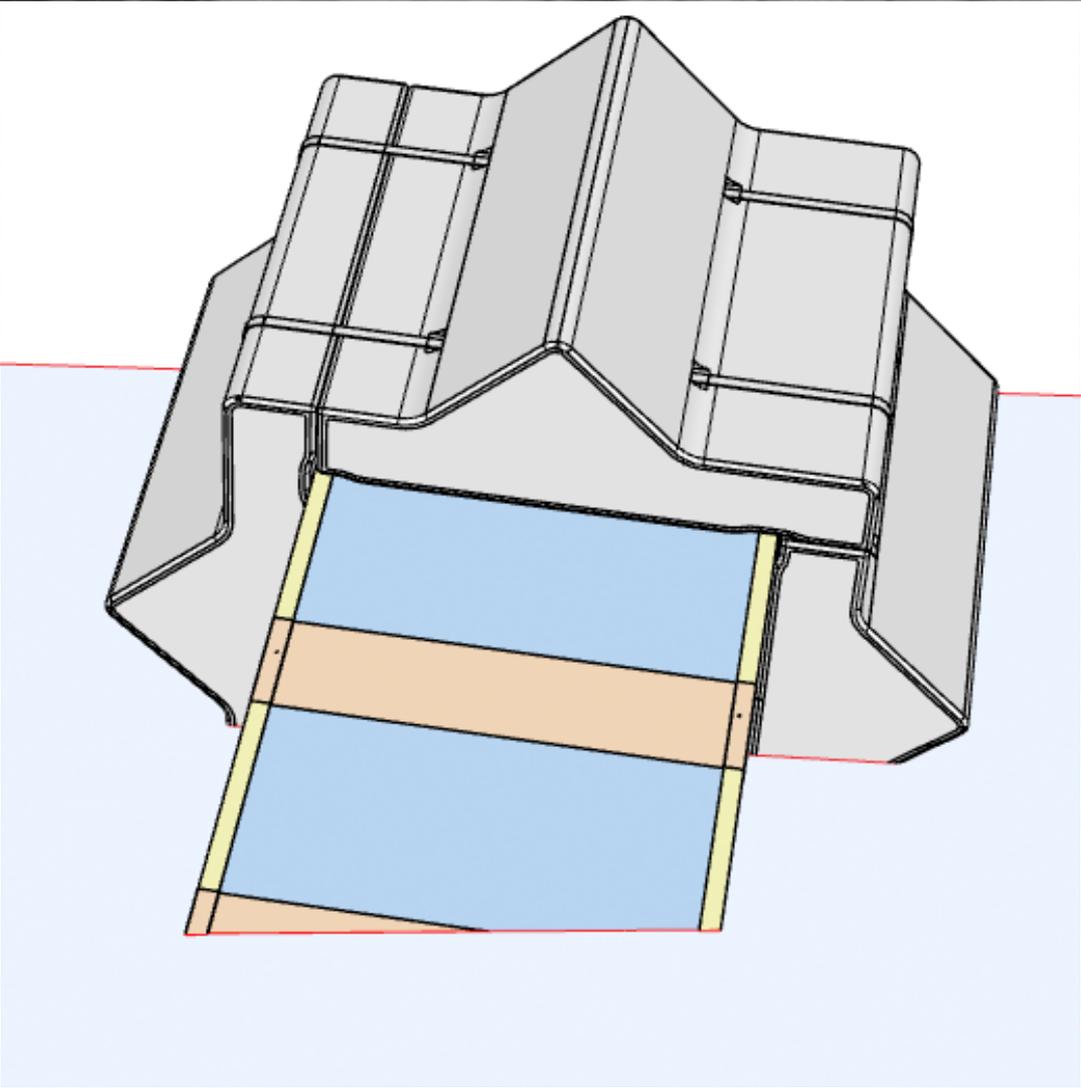


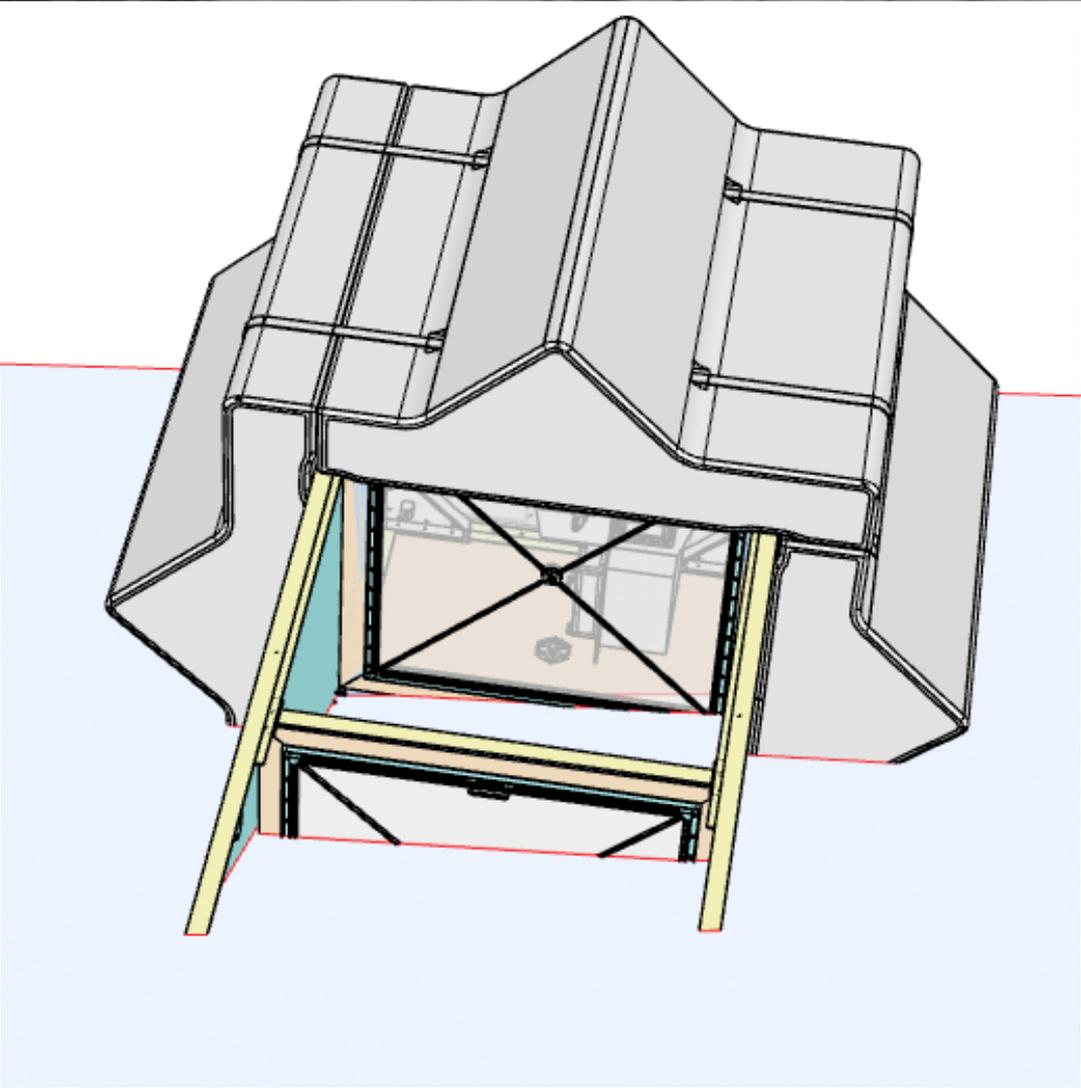


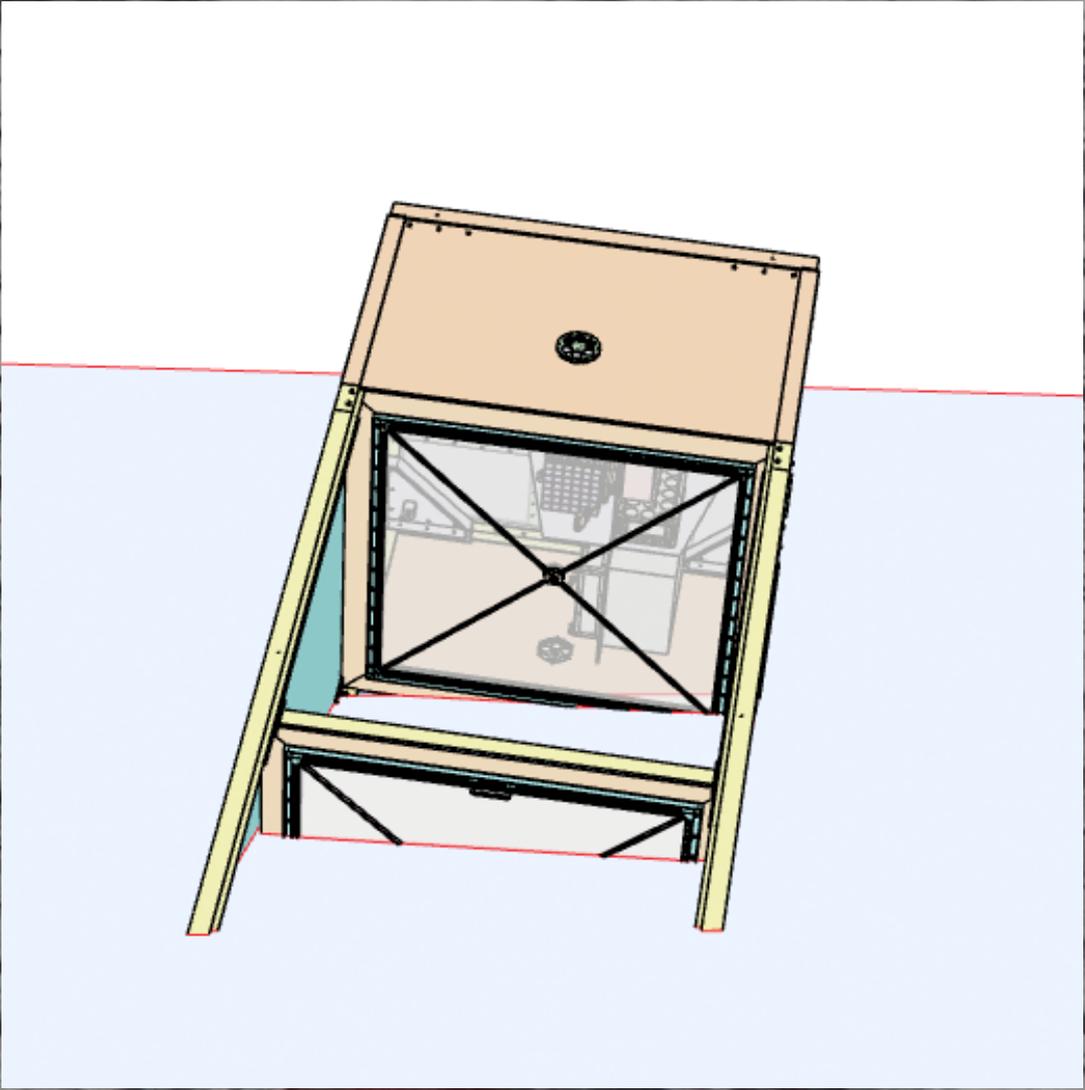
Atter/merrissage : 1% de TM au sol, 99% dans la nacelle













Les données sont dans la boîte !



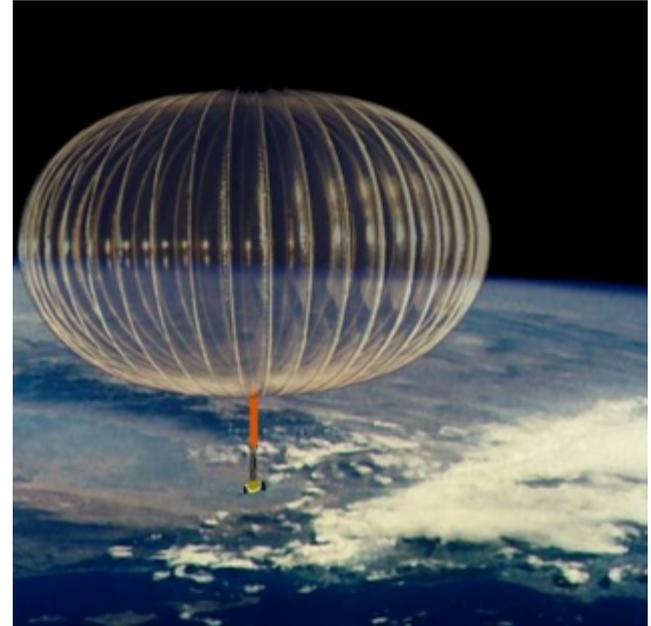


Développement d'une nouvelle version du détecteur PDM

(ASIC v3, FPGA v2, HVPS intégrées)

Mars 2017

Vol 20-30 nuits à bord d'un ballon SPB (NASA), depuis la Nouvelle-Zélande jusqu'en Amérique du Sud, puis Afrique du Sud (Détection de Rayons Cosmiques)



Mai 2017

mini-EUSO, prototype spatialisé à bord de l'ISS (airglow, météores, débris).





L'expérience ne sert-elle qu'à avoir des remords ?

Gérer un projet : utiliser les **soutiens labos** (Cellule de Suivi de Projet, structure matricielle, cellule qualité), les **outils institut** (EDMS/Atrium, Forge, etherpad, Renater (EVO), tableaux de bord, indico, meeting Core, etc.), les **supports de gestion** CNES & CNRS (docs types d'I/F, docs architecture, CR type, liste suivi d'actions), les **applications/logiciels** (redmine, freemind), les **méthodes** de gestion, les **formations**.

Quelques règles générales de bon sens, d'expériences apprises au cours de ce projet :

- **Cahiers des charges** : vision et objectifs clairs = clarifier les besoins.
- Définir **organisation** & rôles (MoU), hiérarchies, objectifs, livraisons (avec interfaces -> ex: Harnais et câbles 😊 !)
- **Phase initiale**: design concourrant, revues de design internes et externes, etc.
- **Prendre les bonnes décisions** (virage difficile), le plus **tôt** possible (on a plus de temps pour rebondir après un problème), avec un **plan B** en tête.
- **Ne pas essayer de tout faire** (vous êtes moins expert, moins endurant, moins résilient qu'une équipe. Exemple de Kobe Briant et des Lakers : chaque fois que Kobe marque plus de 30 points par match, son équipe perd).
- **Attention** : on a tendance à commencer / à faire ce qui est simple, pour ne pas faire ce qui demande une **organisation**, ce pour quoi on n'a pas toujours d'une vision simple et claire de la finalité.



eusoballoon - a wonderful adventure